

PHILIPS



Plasma and Radiation Modelling of EUV Sources for Micro Lithography

Thomas Krücken

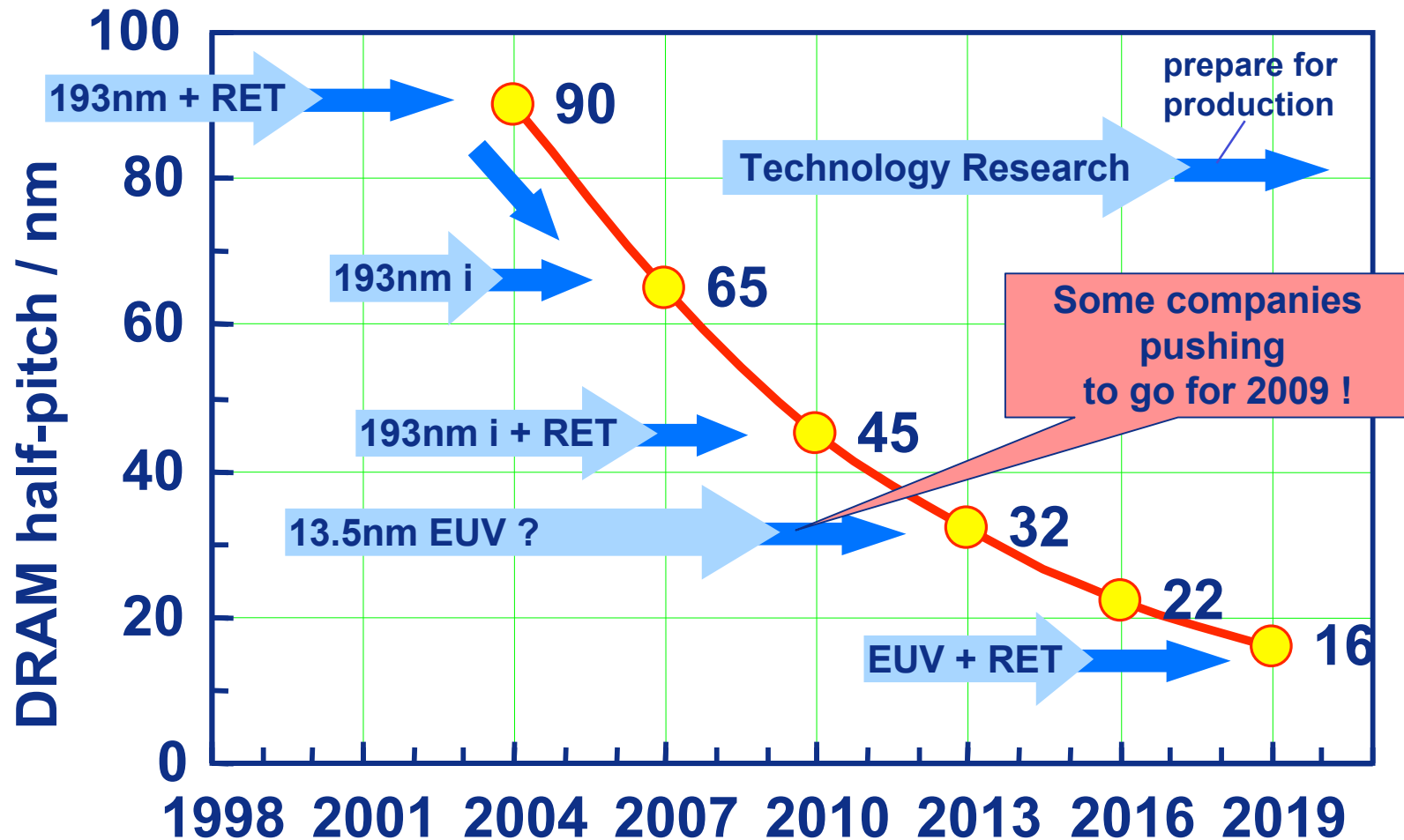
ICAMDATA05, Meudon, France

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Contents

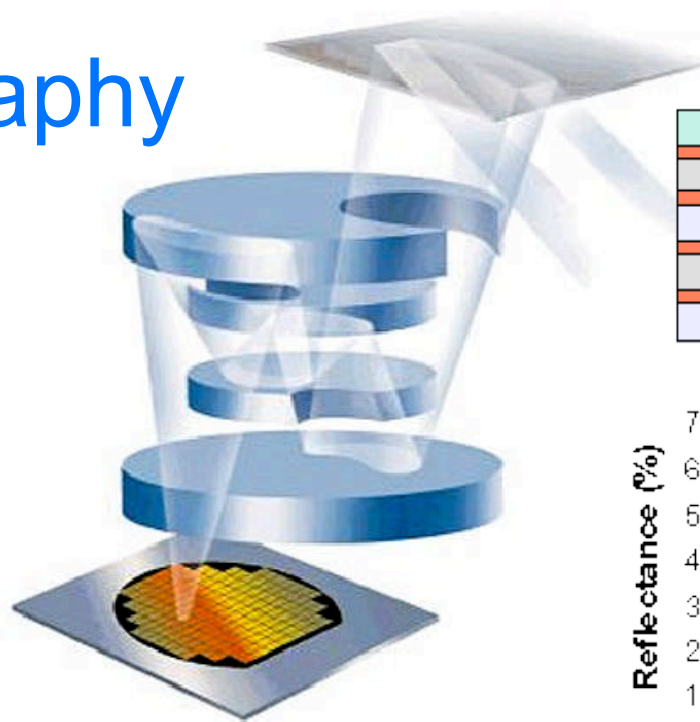
- Requirements of EUV Micro Lithography
- Atomic theory and EUV Radiators
 - Xenon as EUV Radiator
- Very simple plasma model of Xe Pinch Discharge
- Next generation EUV sources, based on Tin
 - Tin as EUV Radiator
 - EUV Source concept
- Current status of EUV Micro Lithography

Semiconductor Roadmap 2003



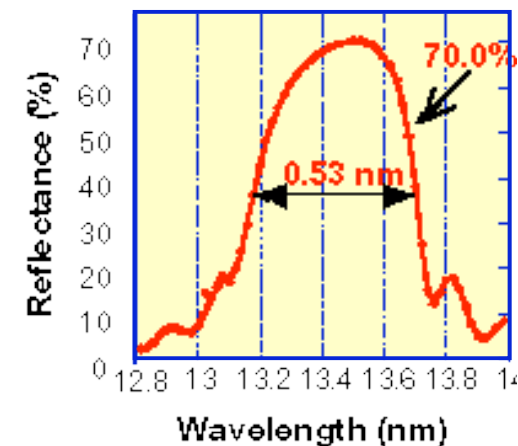
i: Immersion Technology ; RET: Resolution Enhancement Techn

EUV Lithography

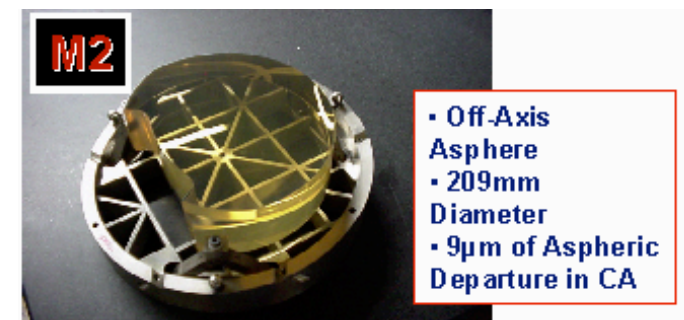


Four-material multilayer

Capping layer
Si layer
Mo layer
Si layer
Mo layer
Si layer
Mo layer
Si layer
Mo layer

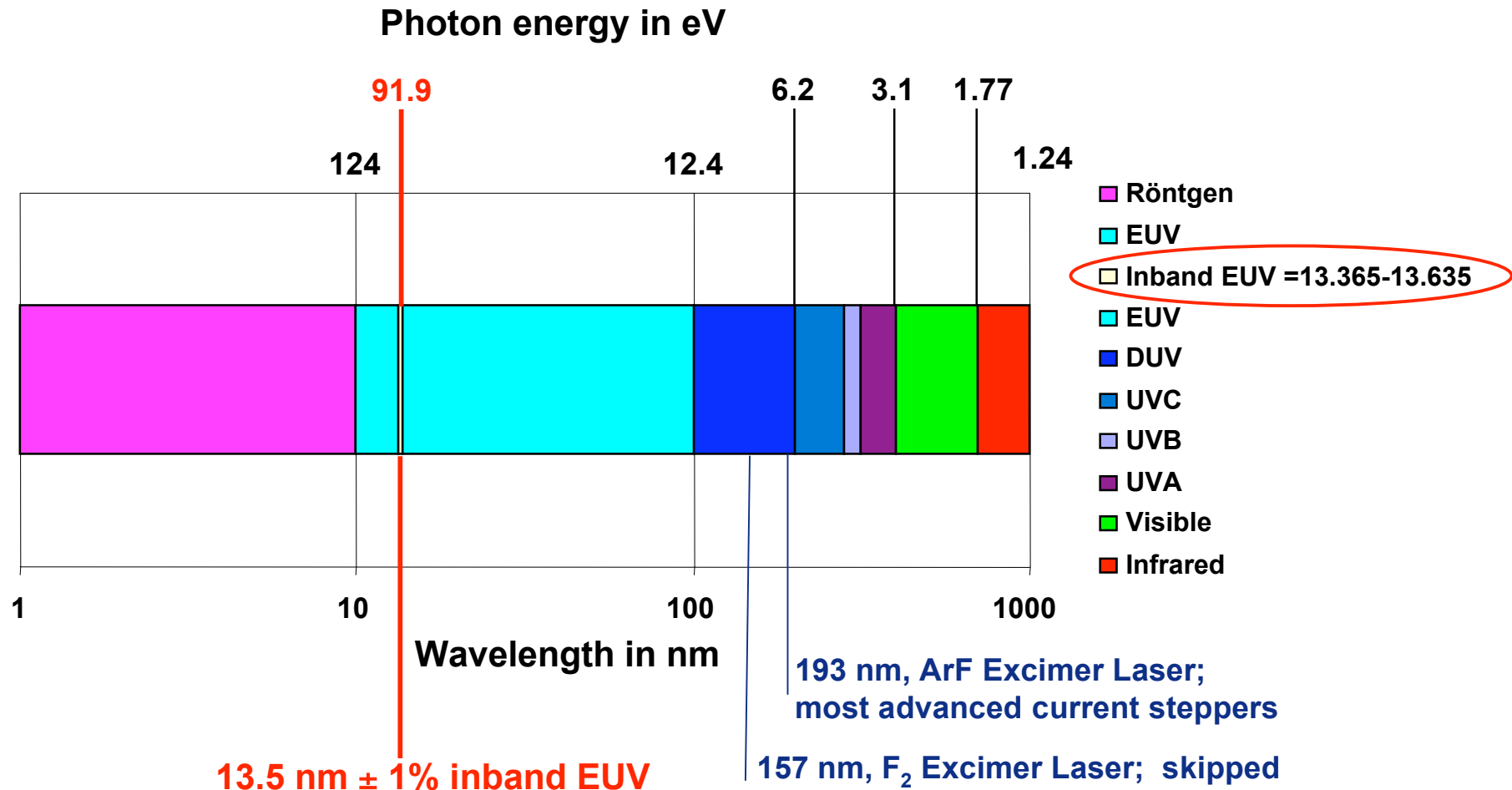


First EUV optics completed



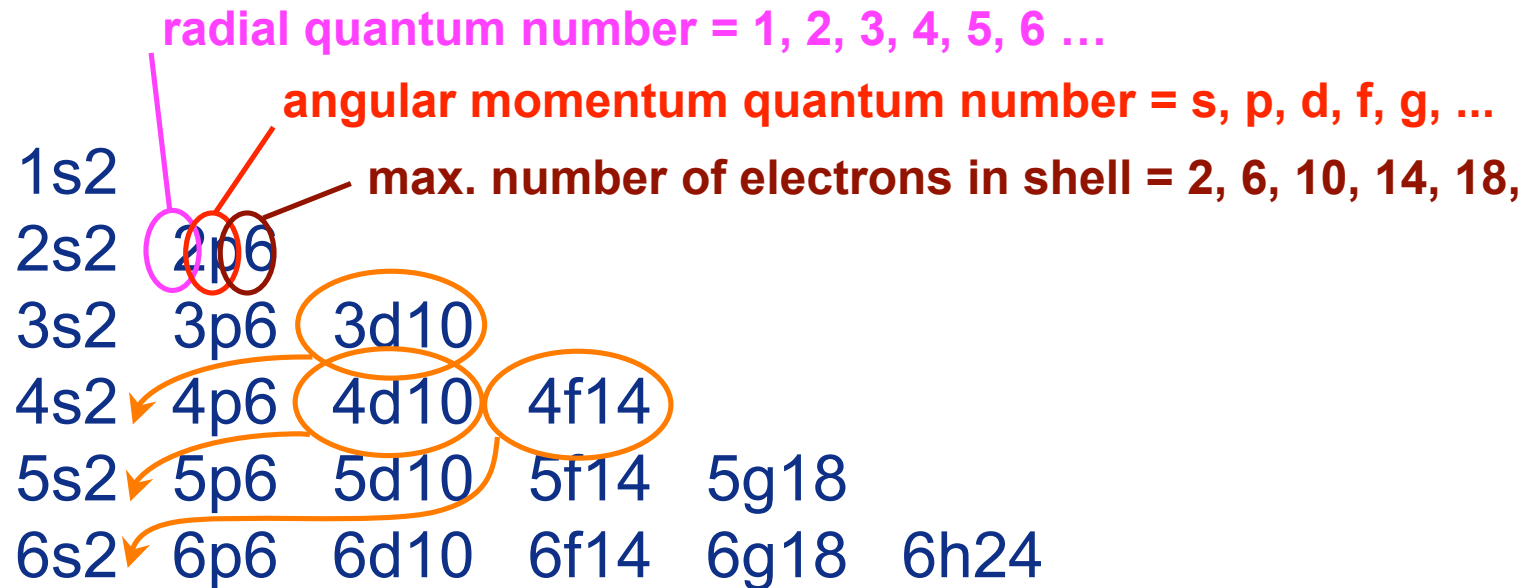
- **Vacuum system**
- **Mirror optics**
 - Grazing incidence
 - Normal incidence
- **Multilayer mirrors available !**
 - for 13.5 nm wavelength
 - bandwidth only ~ 0.5 nm
- **Extreme sub-Nanometer requirements**
 - precision of optical surfaces
 - low (zero) thermal expansion

EUV wavelength and Photon energy range

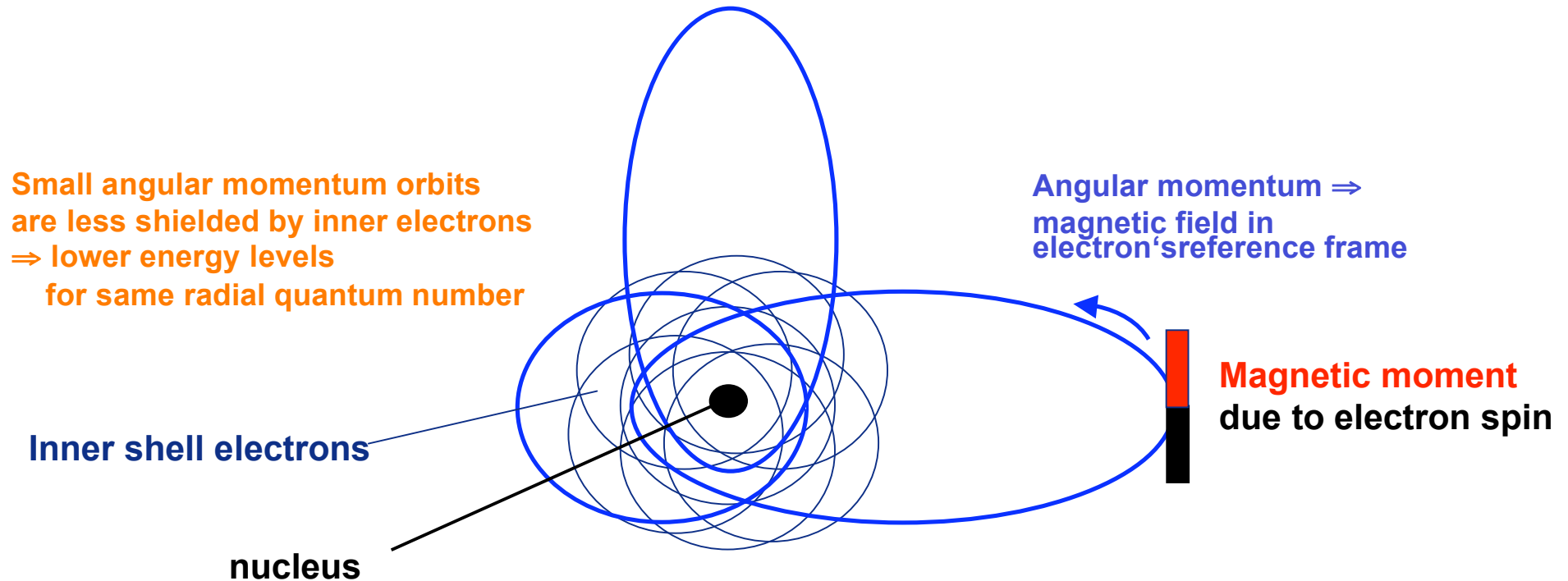


Conversion Efficacy = CE = inband EUV radiation in 2π / input pov

Periodic table of elements, electron configurations



Angular momentum of outer shell electrons



- Number of energy levels per configuration determined by total angular momentum conservation and Pauli principle
- Half filled outer shells with high angular momentum have many energy levels ⇒ „grass-like“ spectra

Atomic plasma physics package

ADAS,

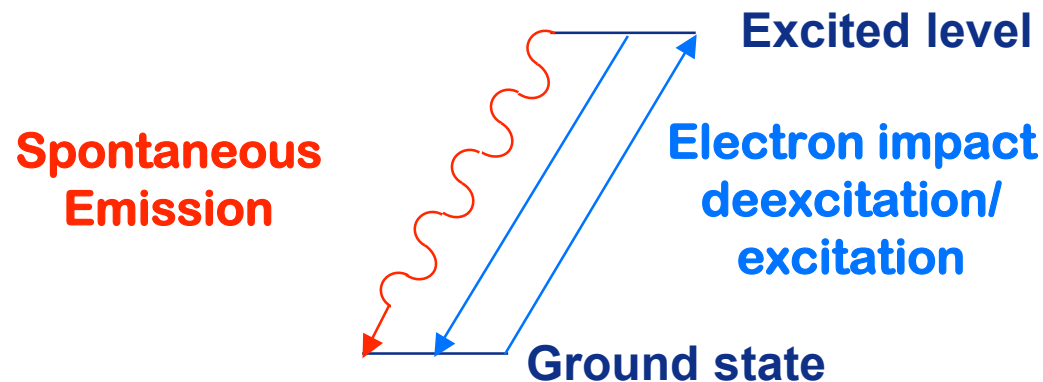
University of Strathclyde, Glasgow

1. Step: Calculation of energy levels and transitions

- Based on **Cowan-O'Mullane Hartree-Fock** atomic structure code
- Input: Electron Configurations, i.e. Xe^{10+} :
 - 4s² 4p⁶ 4d⁸ (ground state configuration)
 - 4s² 4p⁶ 4d⁷ 4f¹
 - 4s² 4p⁶ 4d⁷ 5s¹
 - 4s² 4p⁶ 4d⁷ 5p¹
 - 4s² 4p⁶ 4d⁷ 5d¹
 - 4s² 4p⁵ 4d⁹
 - **Exact calculation of 4f-levels requires even more configurations**
- Calculates energy levels incl. HFS like Spin-Orbit coupling, up to 1200 levels per ion stage, **accuracy ~ 0.3 nm ...**
- Calculates photonic Transitions, i.e. A-values, between all levels for el. Dipole, mag. Dipole, up to 300000 transitions
- Calculates excitation/dexcitation rates by (Maxwellian) electron impact for all transitions in Born-Oppenheimer approximation
- Results are stored in file for further use

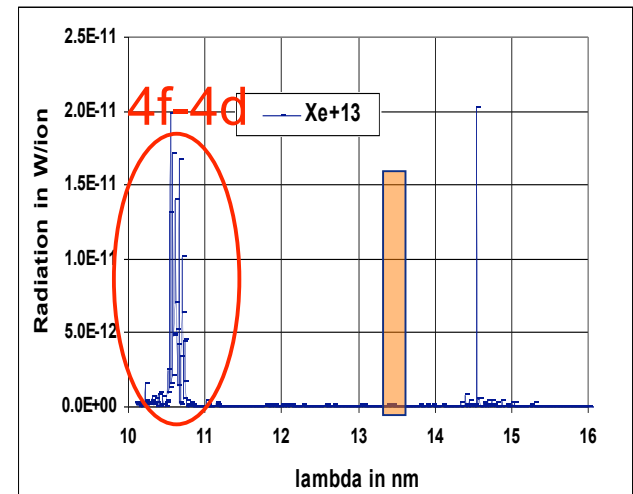
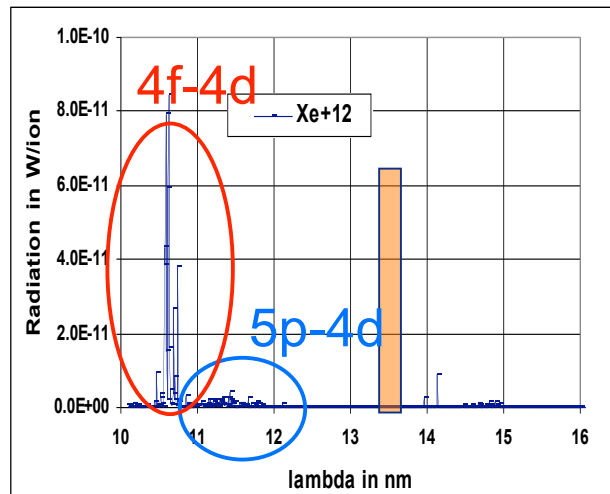
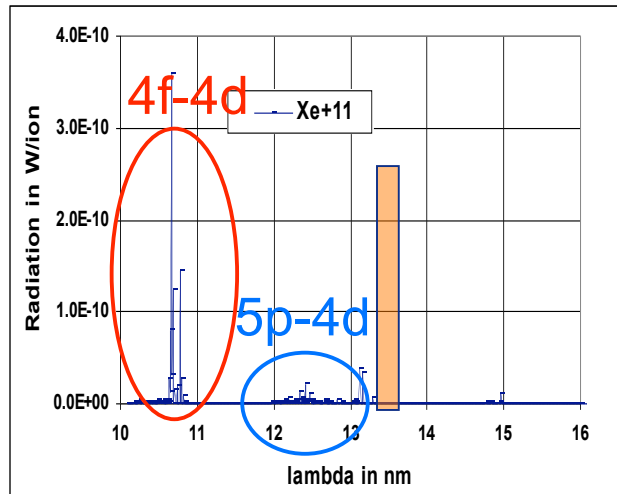
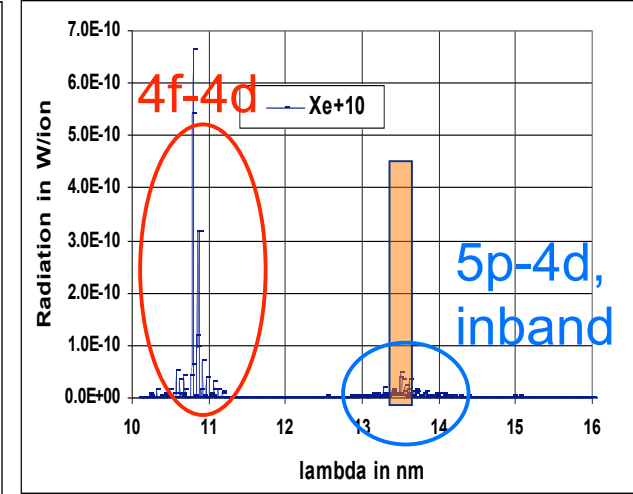
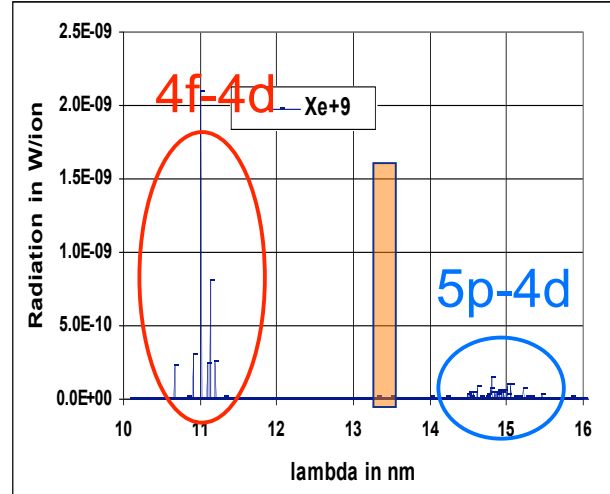
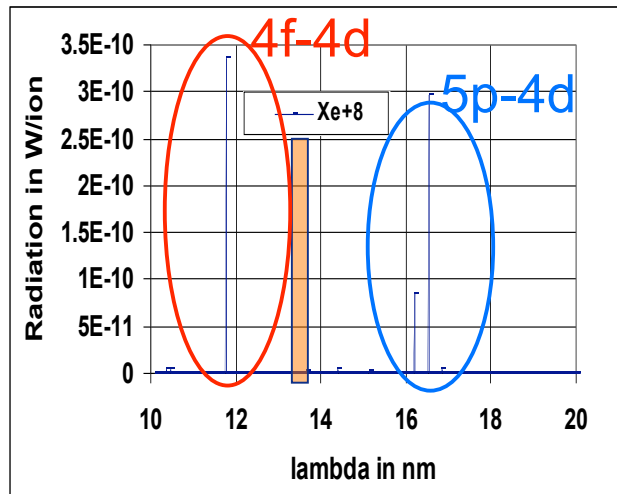
2. Step: Excited states population and spectra

- Balances all processes, i.e. calculates collisional radiative population equilibrium as function of T_e , n_e



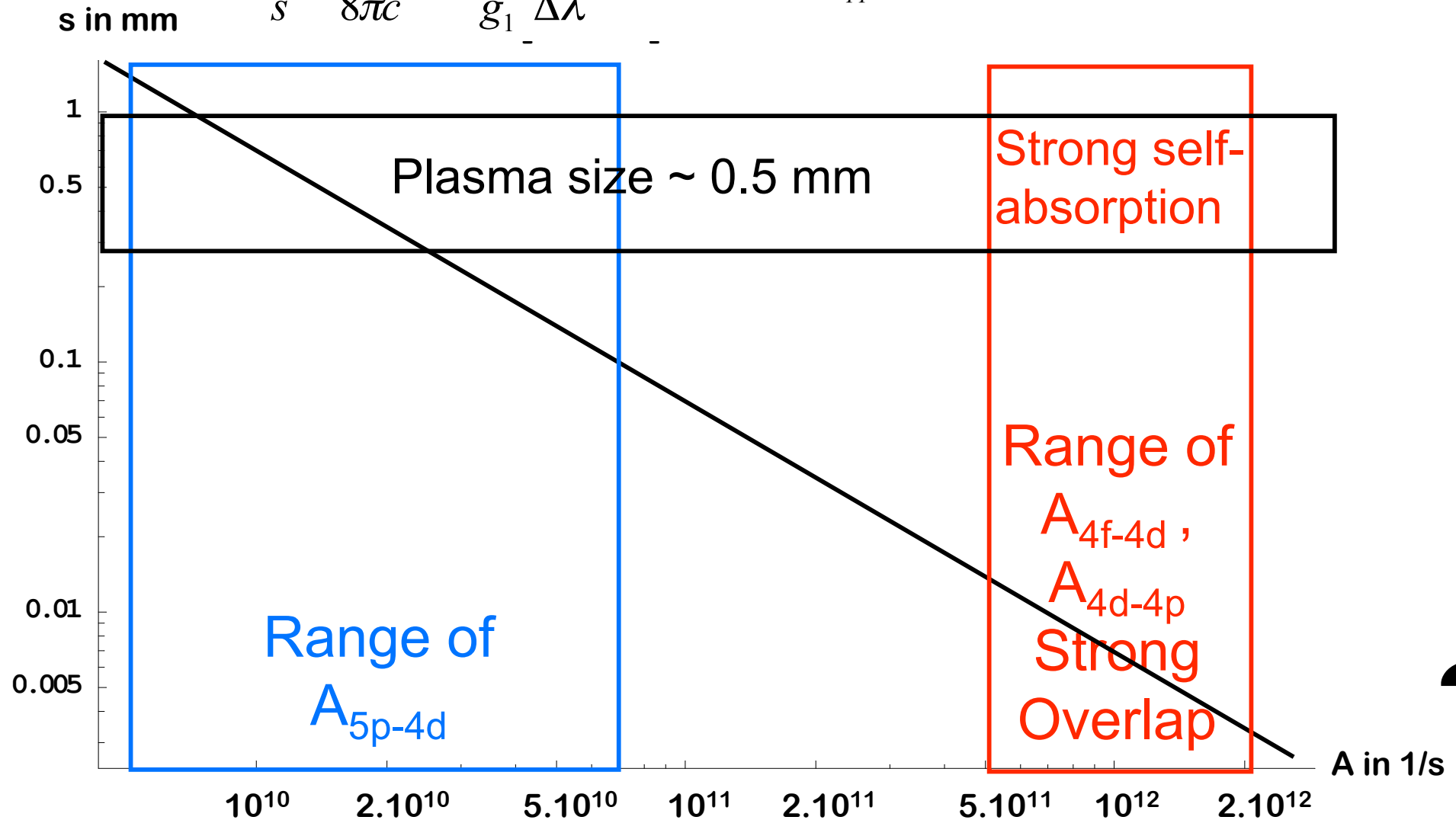
- Transition Corona / CR / LTE
- From an excited states population total radiated power and emission spectra of individual ions are calculated

Optically thin Spectra of $\text{Xe}^{+8} - \text{Xe}^{+13}$ ions; $T_e = 32 \text{ eV}$, $n_e = 10^{17}/\text{cm}^3$

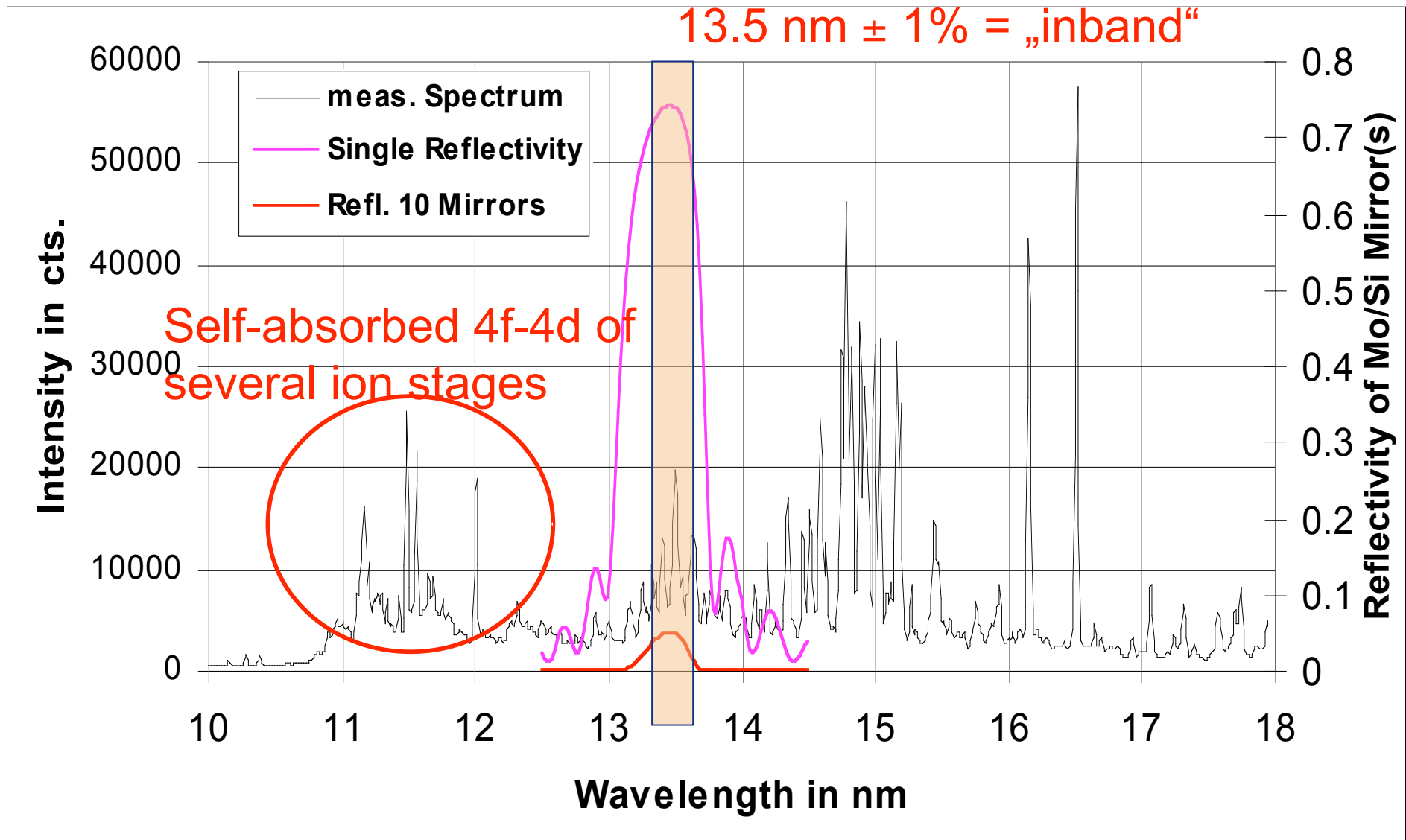


Opacity / Optical Depth s , $n=10^{17}/\text{cm}^3$;

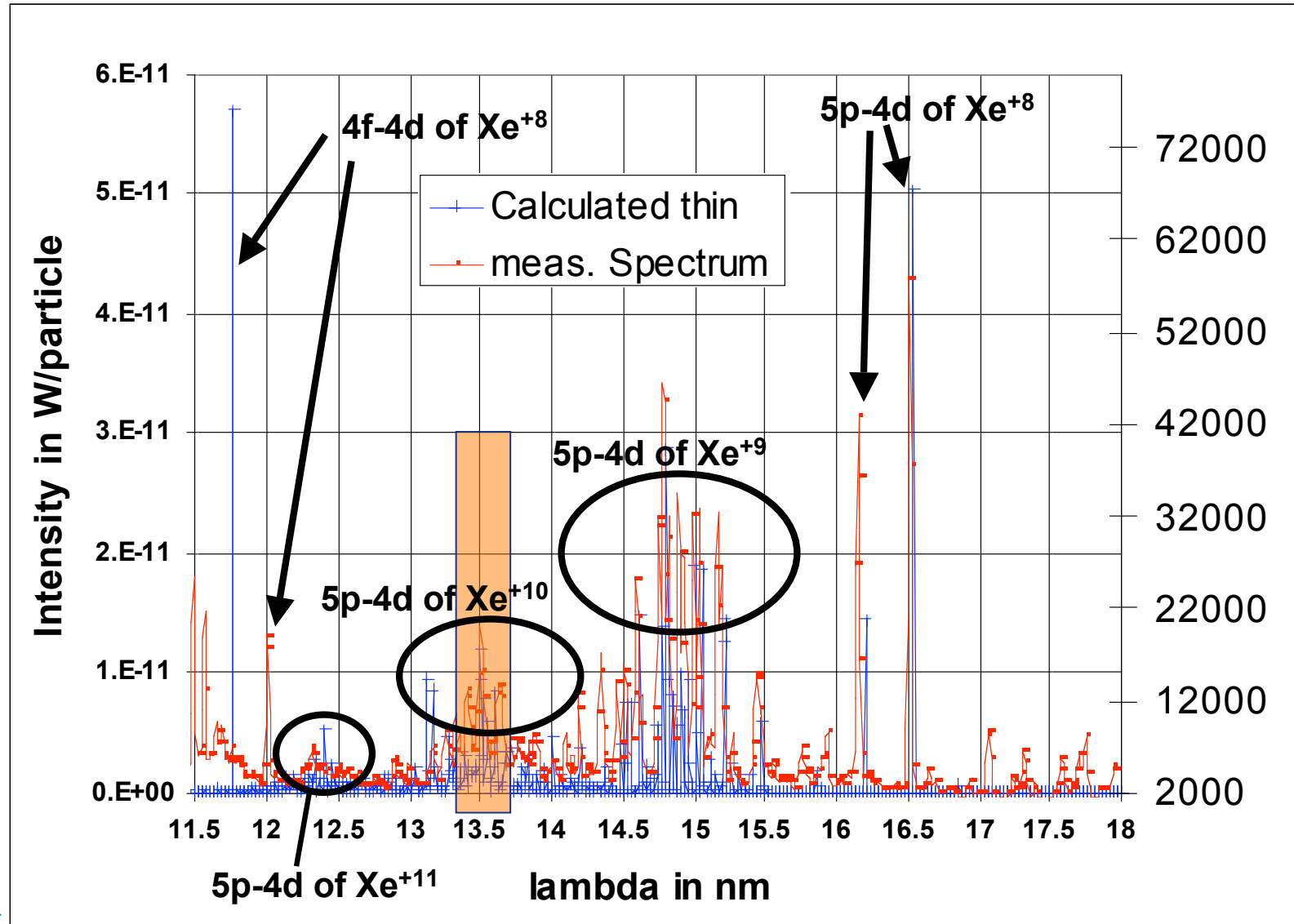
$$\frac{1}{s} = \frac{\lambda^4}{8\pi c} A_{21} \frac{g_2}{g_1} \frac{n}{\Delta\lambda}, \quad \Delta\lambda = \Delta\lambda_{\text{Doppler}} (T = 1000\text{eV}) \sim 3\text{pm}$$



Measured EUV Spectrum of Xe



Thin Xe spectrum of ion mix near 13.5 nm



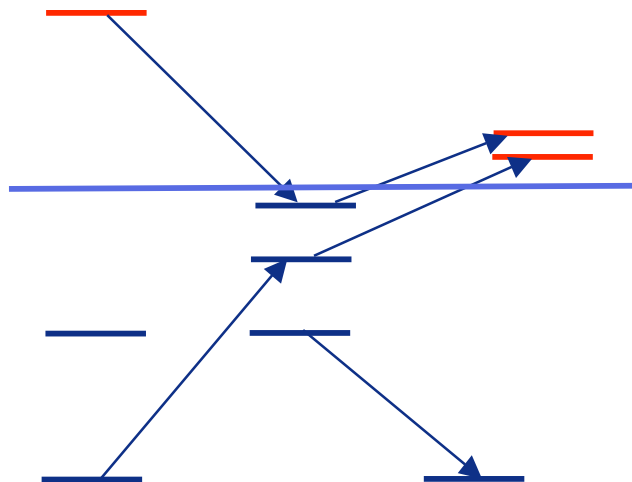
Most important Spectral properties

- 5p-4d transitions
 - Energy levels depend on ionization stage
 - Can be calculated with good accuracy
 - Some absorption of photons $\Rightarrow$ escape factors reduce A-values
 - Escape factors can then be used to calculate population, spectral parts due to these transitions
- 4f-4d/4d-4p transitions
 - Large overlaps of wavefunctions for higher ionization stages $>+4$:
 - Then: Little dependence of levels on ionization stage
 - Exact calculation of energy levels requires inclusion of many configurations
 - High angular momentum $\Rightarrow$ many levels/transitions for half-filled outer shells
 - Large A-values $\Rightarrow$ strong self absorption

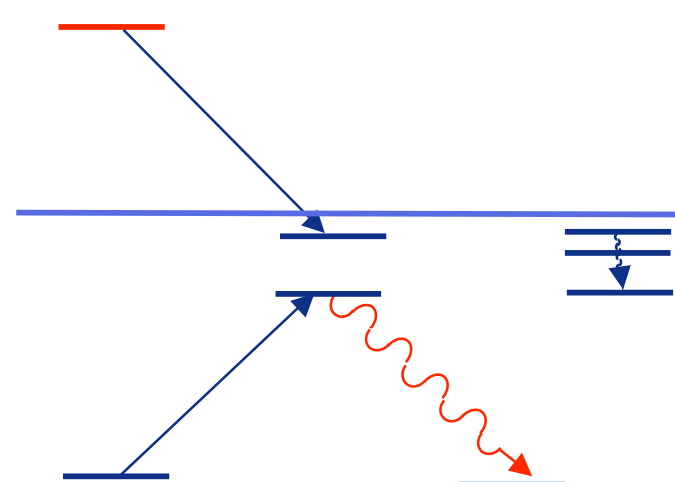
Ionisation / Recombination

- Most difficult, current subject of research
 - influence of metastables, typically other spin-system,
 - dielectronic processes very important
 - depend on many intermediate states with high n
 - influence of inner shell electrons

Dielectronic ionisation

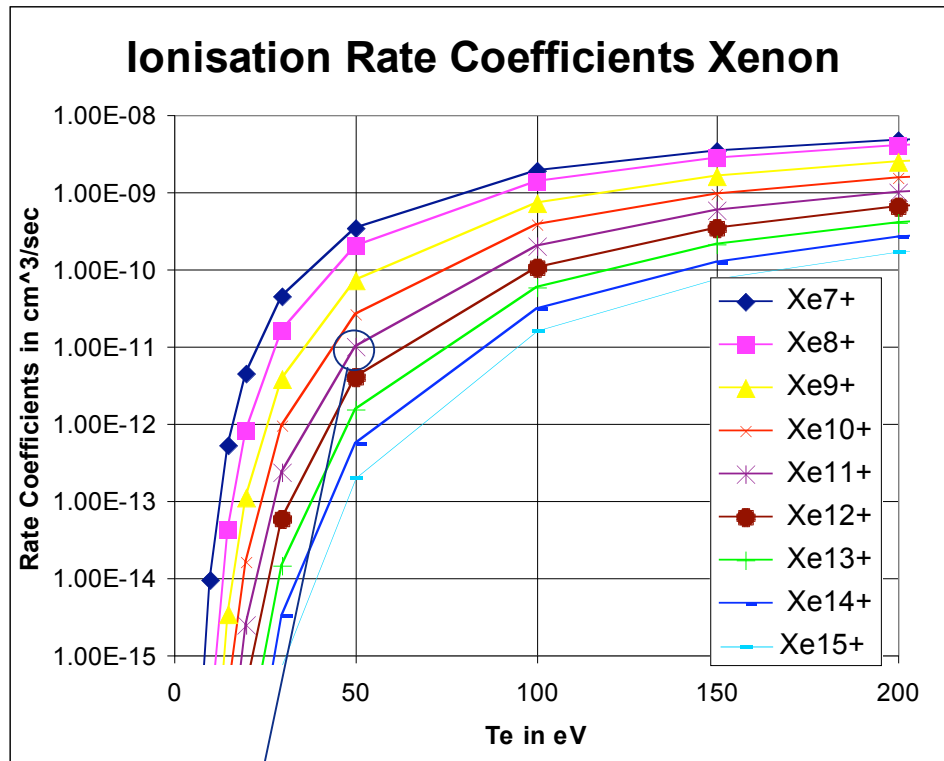


Dielectronic recombination

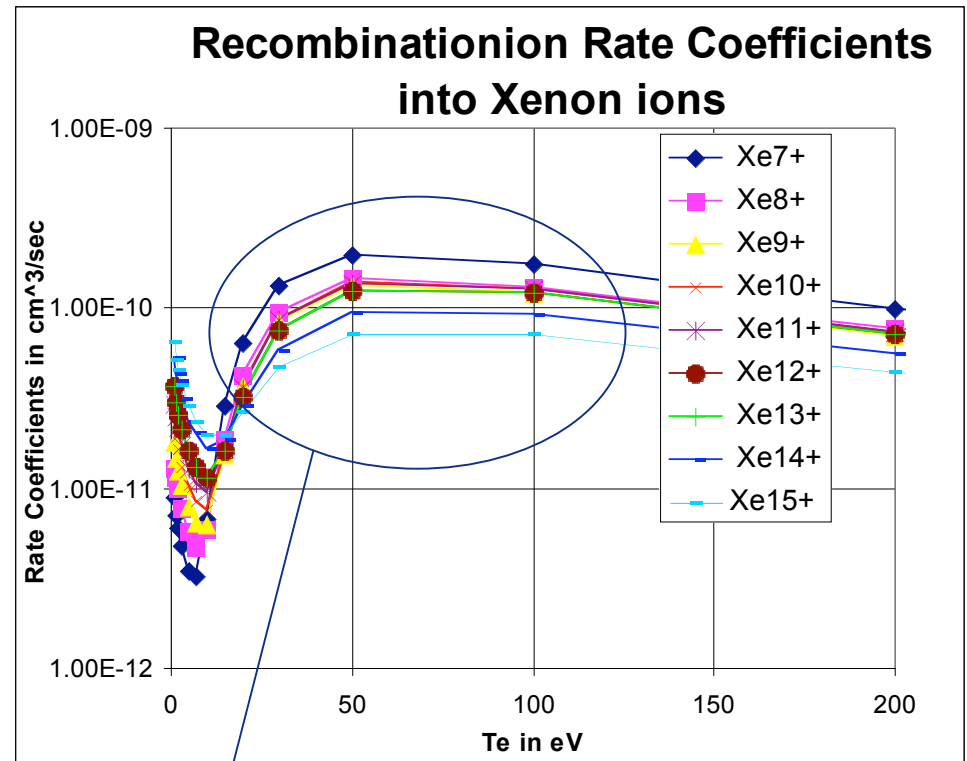


- ADAS evaluates effective ionisation coefficients
- complicated advanced calculations to obtain higher accuracy ($< 50\%$)

Ionisation/recombination rates of Xe-ions from ADAS



For $n_e = 10^{18}$, $T_e = 50$ eV:
 $\tau_{\text{ion}} \sim 100$ ns

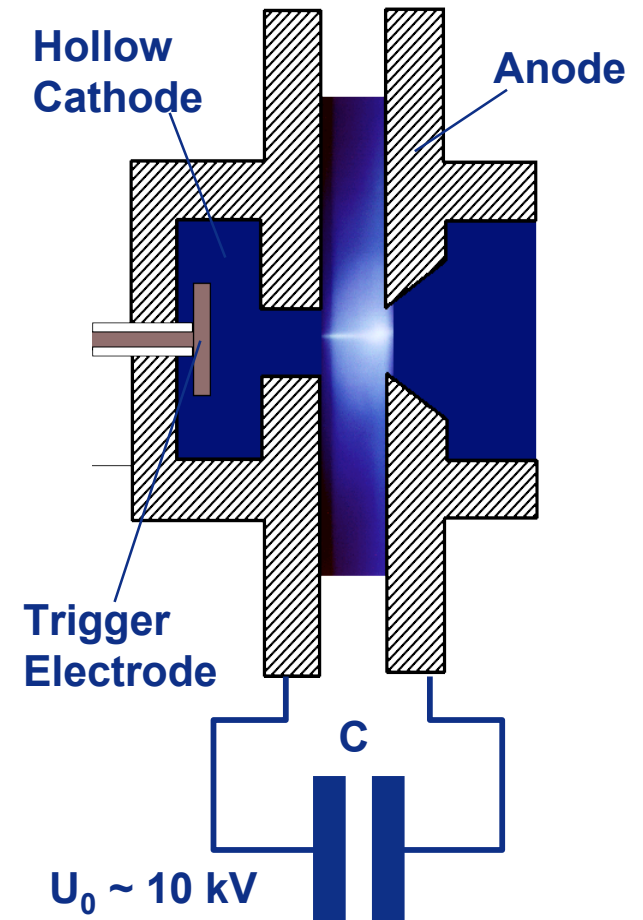
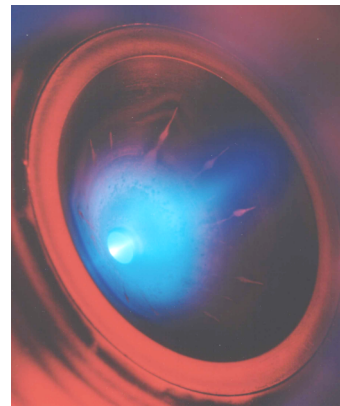


Dielectronic contributions

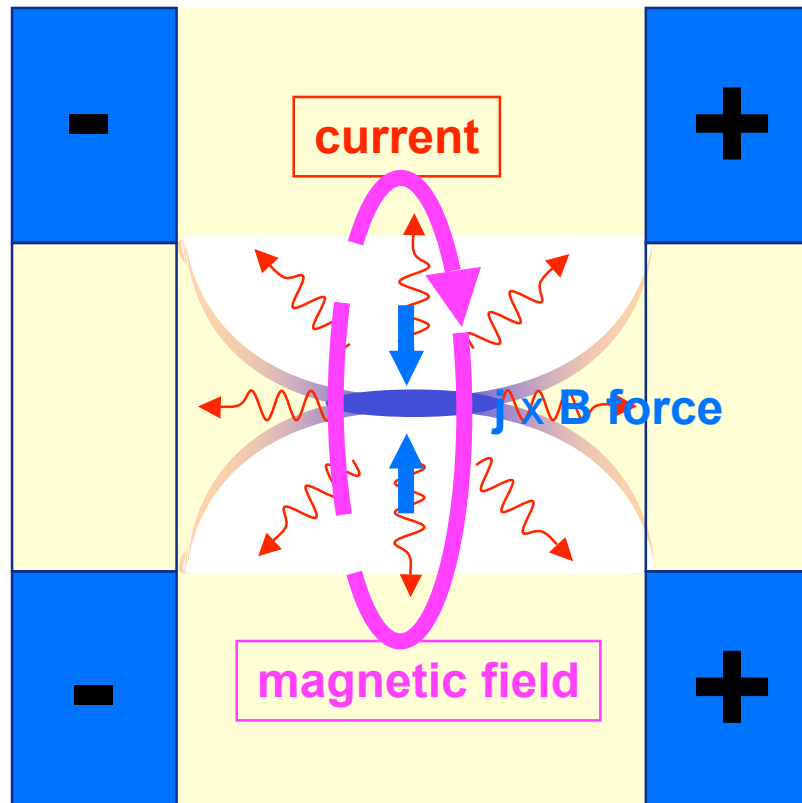
Philips Extreme UV: HCT Pinch as source

"Hollow Cathode Triggered Pinch"

- **Hollow Cathode**
 - defined ignition & triggering
 - **cold pressure ~ 10 Pa**
- **High current pinch discharge**
 - "pseudo spark discharge"
 - production of hot plasma by magnetic (self-)compression
 - intense EUV radiation



Pinch Phase after ignition



- Magnetic compression (pinching) of Xe plasma
- Current several kA during pinch phase
- Pinch time $\sim 100\text{ns}$
- $T_e \sim 50\text{eV}$, $n_e \sim 10^{18}/\text{cm}^3$

Implosion times and current characteristics must be matched
 $\Rightarrow$ Current maximum during minimum plasma radius

Electrical circuit

circuit equations, L_0 , R_0 , C_0 , coupled to
pinch with $L(t)$, $R(t)$; Bypass with $R_{bypass}(t)$

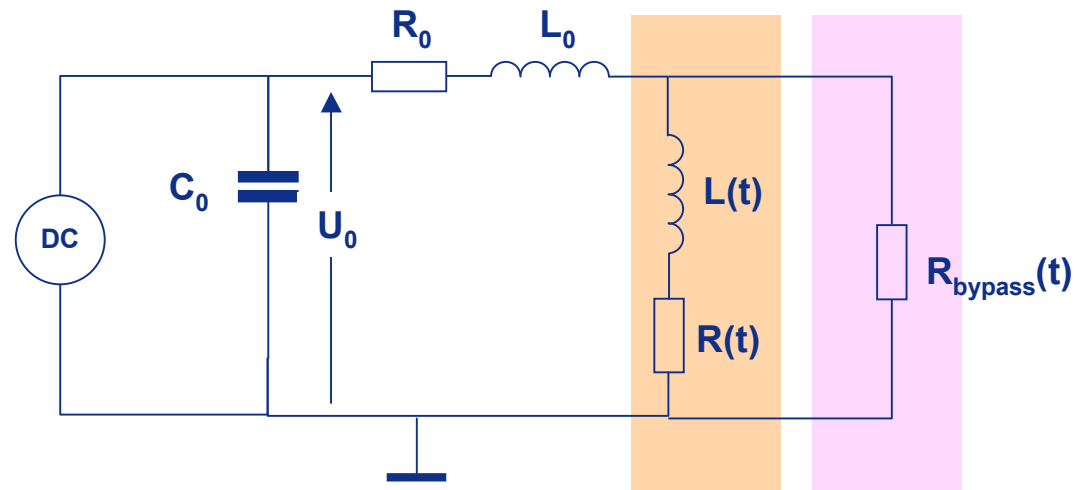
Total Energy
per pulse:

$$E = \frac{1}{2} C_0 U_0^2$$

$$\frac{dU_0}{dt} = -I_{tot} / C_0$$

$$U_0 = L_0 \frac{dI_{tot}}{dt} + R_0 I_{tot} + L \frac{dI}{dt} + \left(R + \frac{dL}{dt} \right) \cdot I$$

$$R_{Bypass} (I_{tot} - I) = L \frac{dI}{dt} + \left(R + \frac{dL}{dt} \right) \cdot I$$



$$\tau_{Period} \sim 2\pi \sqrt{L_0 C_0}$$

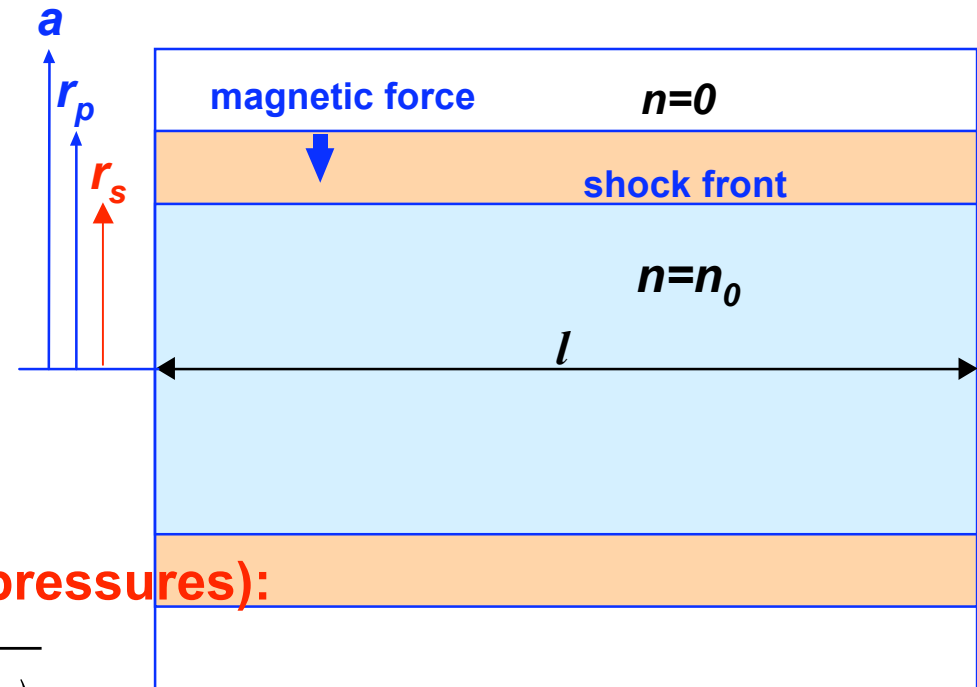
Simple Zero Dimensional Dynamic Pinch Model

Supersonic implosion phase, snowplough with shock front preceding magnetic piston,

No radial or axial profiles;

Momentum equation, piston radius r_p , starting at a :

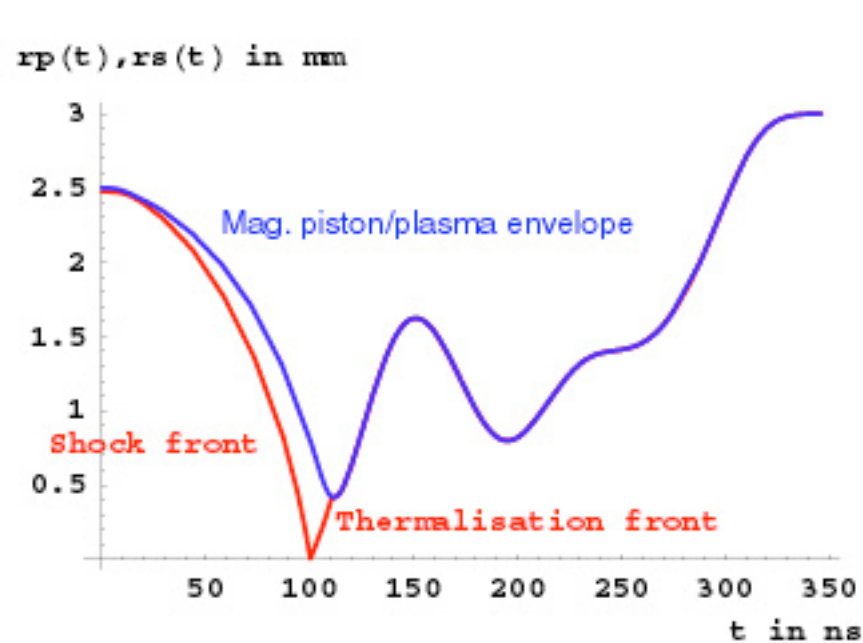
$$N \frac{d}{dt} \left(M_{atom} \left(1 - \frac{r_s^2}{a^2} \right) v_p \right) = 2\pi l r_p \cdot (p_{therm} - p_{mag})$$



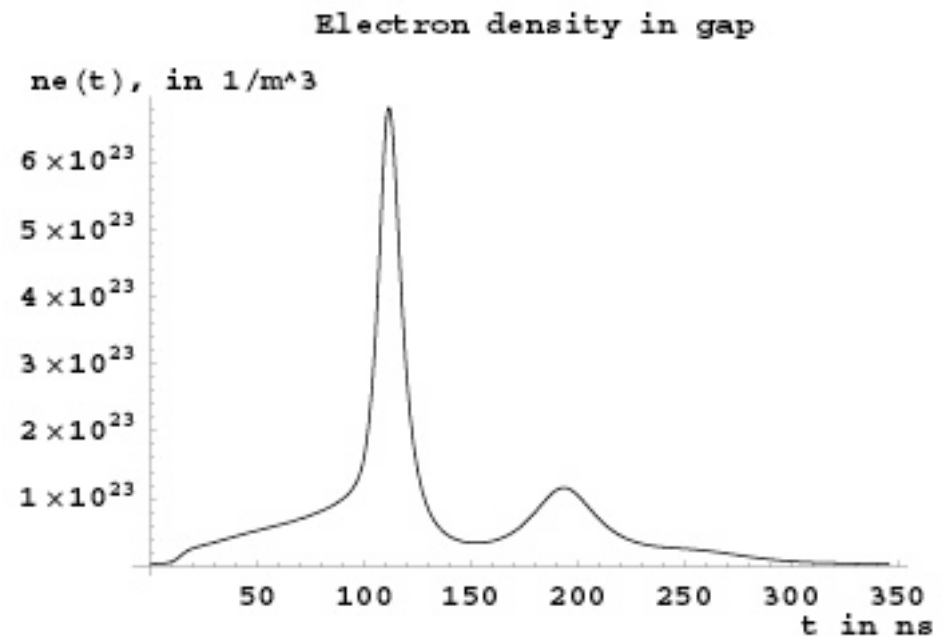
Equation for shock front radius r_s
(equilibrium of thermal and impact pressures):

$$v_s = \dot{r}_s = - \sqrt{\frac{k(ZT_e + T_i)}{M_{atom}} \frac{(a^2 - r_p^2)}{(r_p^2 - r_s^2)}}$$

Pinch Radii and Electron density



Velocities of order ~ 20000 m/sec



Electron density changes very fast

Zero Dimensional Dynamic Pinch Model

Energy equations for electron Temperature:

$$N \frac{d}{dt} \left[\frac{3}{2} k Z T_e + E_{ion}(Z) \right] = R \cdot I(t)^2 - p_e dV - Q_{ei} - \sum_i A_{ionstage} \cdot U_{rad,ionstage}(N, T_e, n_e)$$

$$U_{rad,ionstage}(N, T_e, n_e)$$

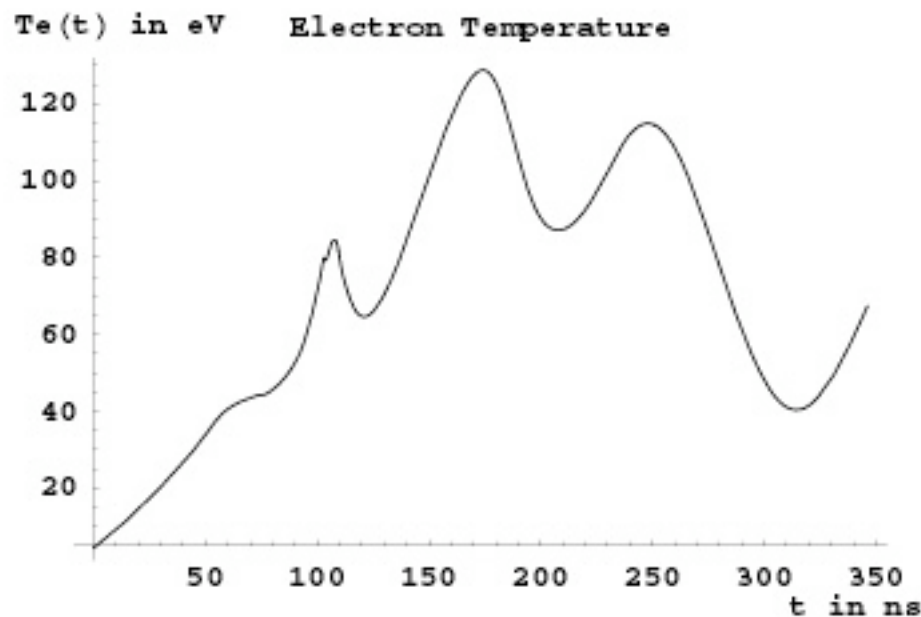
Radiation Power, tabulated from ADAS, based on CR population of excited states of each ionisation stage

R : Spitzer Resistivity; Q_{ei} : Energy exchange electrons-ions

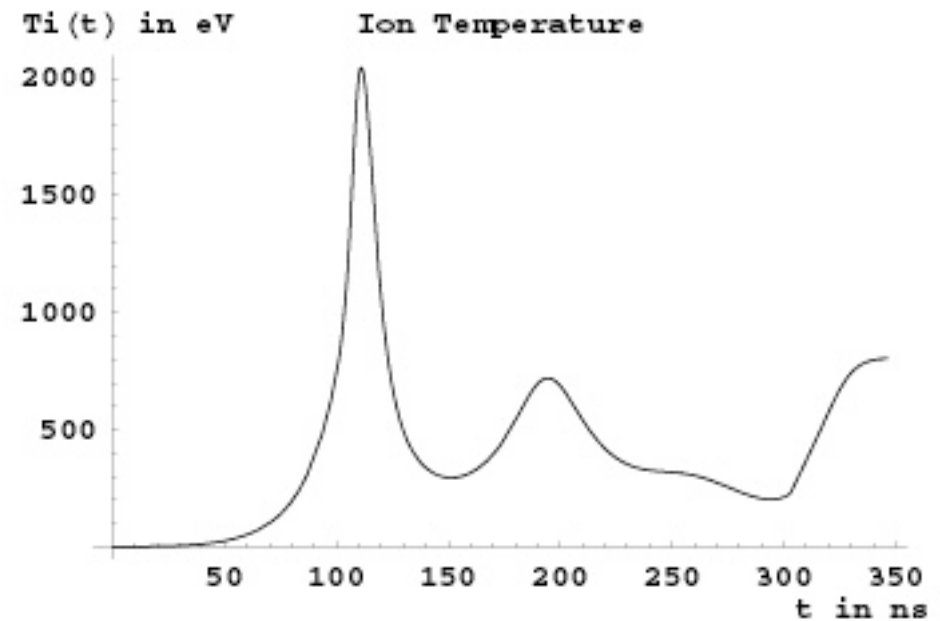
Energy equations for ion Temperature:

$$N \frac{d}{dt} \left[\frac{3}{2} k T_i \right] = -N M_{atom} \frac{r_s v_s}{a^2} v_p^2 - p_i dV + Q_{ei}$$

Temperatures of Electrons/Ions



**Electrons mostly heated ohmically,
loose energy via ionisation, radiation**



**Ions heated by magnetic
compression/shock heating,
mostly hotter than electrons
energy transferred to
electrons at high densities**

Zero Dimensional Dynamic Pinch Model

Ionisation dynamics to compute abundancies $A_{ionstage}$ of all ion stages:

$$\frac{dA_{ionstage}}{dt} = n_e \cdot \left(A_{ionstage-1} \cdot IR_{ionstage-1}(T_e) - A_{ionstage} \cdot IR_{ionstage}(T_e) + A_{ionstage+1} \cdot RR_{ionstage+1}(T_e) - A_{ionstage} \cdot RR_{ionstage}(T_e) \right)$$

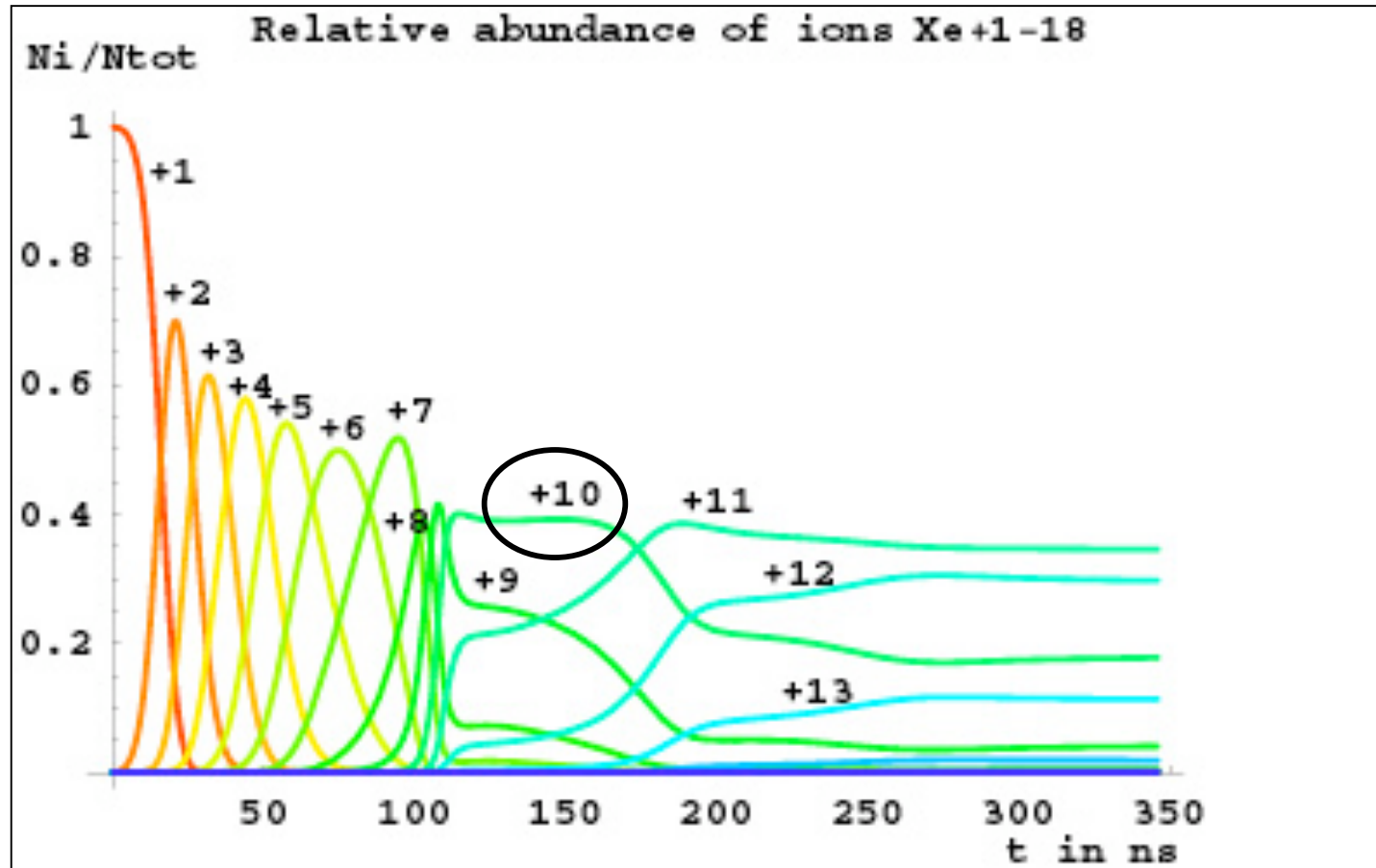
$$IR_{ionstage}, RR_{ionstage} :$$

Ionisation and Recombination rates of each ionisation stage, including dielectronic processes, tabulated from ADAS

Axial Particle Losses:

$$\frac{dN}{dt} = -2N \frac{v_{th,i}(T_i)}{l}$$

Ionisation dynamics



Ionisation/recombination must be treated dynamically
Abundance of Xe⁺¹⁰ optimized, but < 40 %

Bypass caused by Photoionisation of outer gas

Dynamic ionisation of outer gas

$$\frac{dZ_{out}}{dt} = \sigma_{PhotoIonisation} \cdot PhotonFlux \cdot \theta(h\nu - E_{ion}(Z_{out}))$$

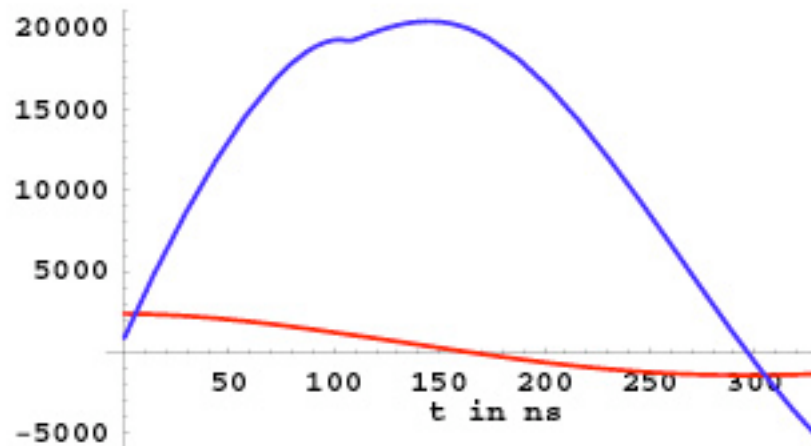
Bypass Resistance: electrode fall + collisionless, quasineutral plasma

$$R_{Bypass} \cdot I_{Bypass} = V_{Bypass} = V_{Fall,By} + \frac{m_e}{2e} \left(\frac{j_{Bypass}}{e \cdot Z_{out} \cdot n_0} \right)^2$$

Current/Voltage Characteristics

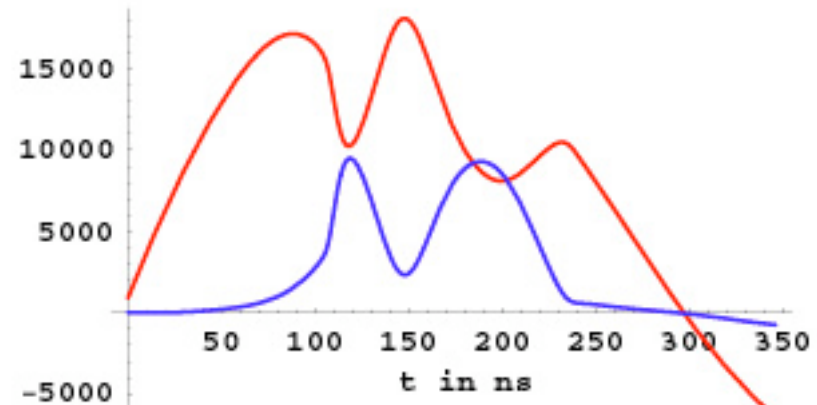
Voltage/Current Characteristics

$U(t), I(t)$ in V,A



Pinch and Bypass Currents

$IPinch(t), IBypass(t)$ in A

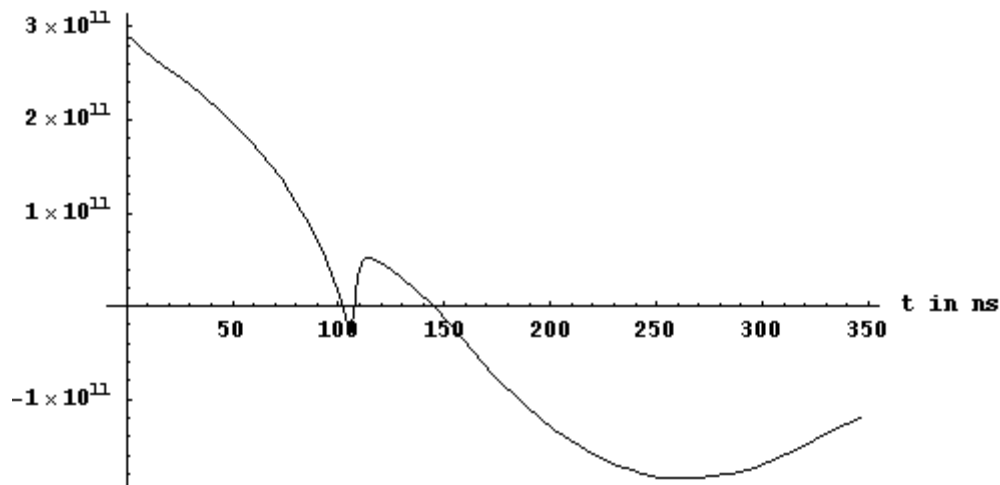


Important comparison with measurements,
agreement requires bypass currents

Photoionisation of outer gas
opens Bypass channel

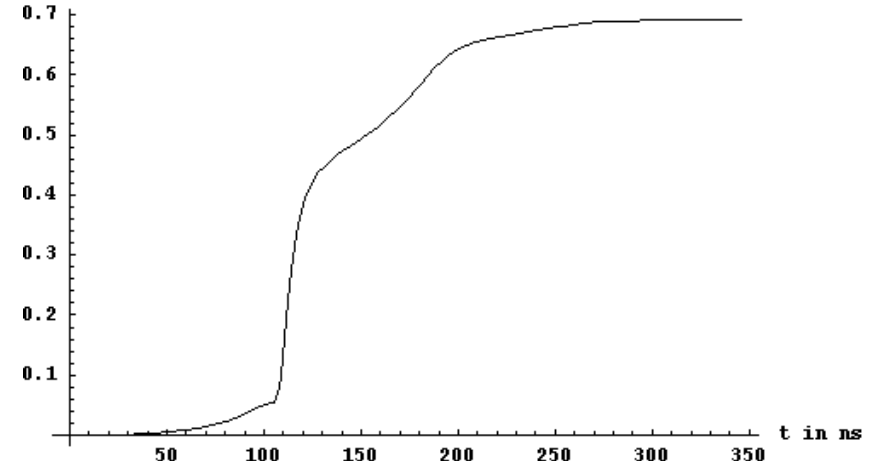
dI/dt , in A/sec

dI/dt

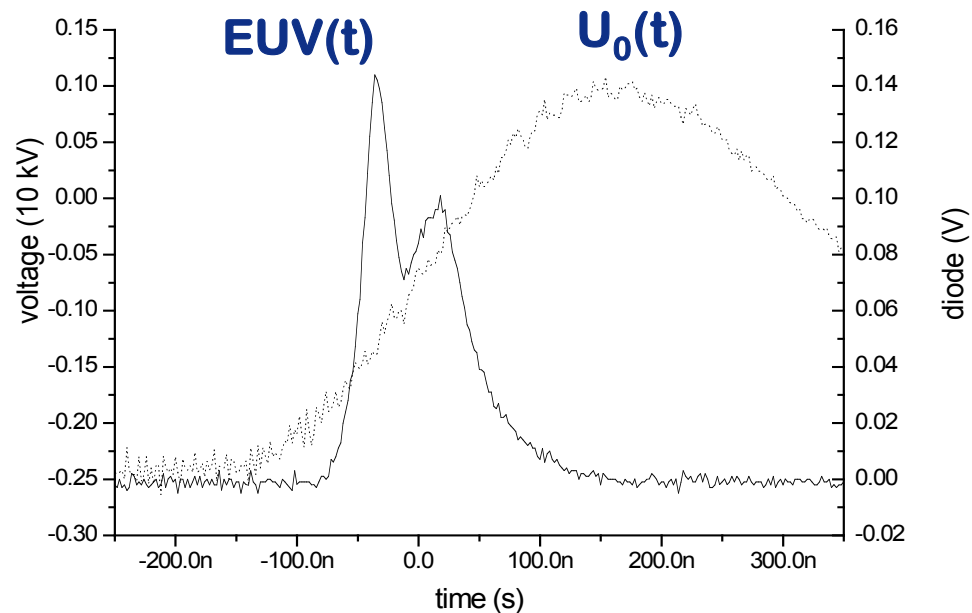
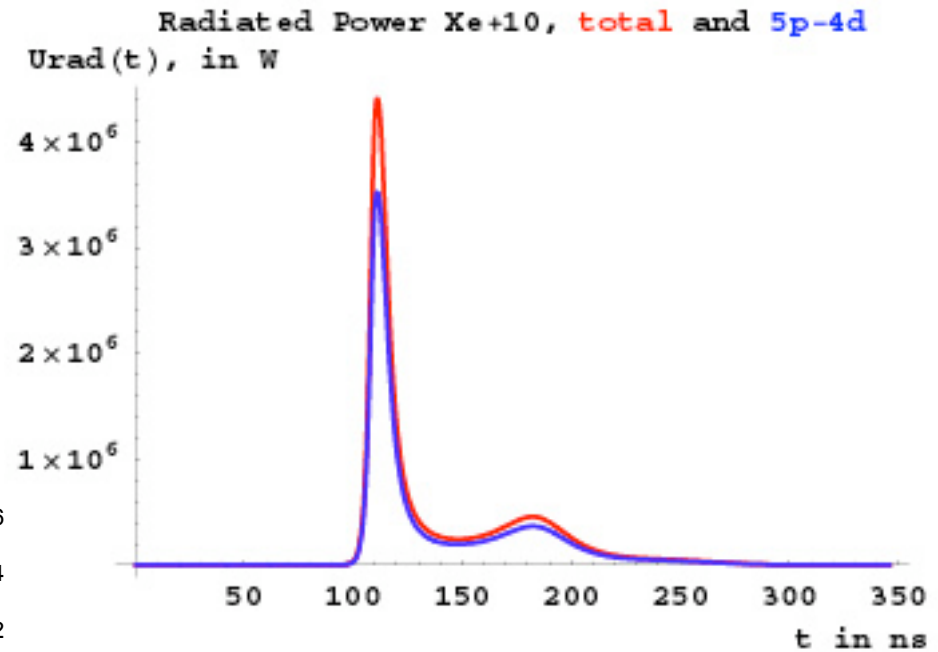
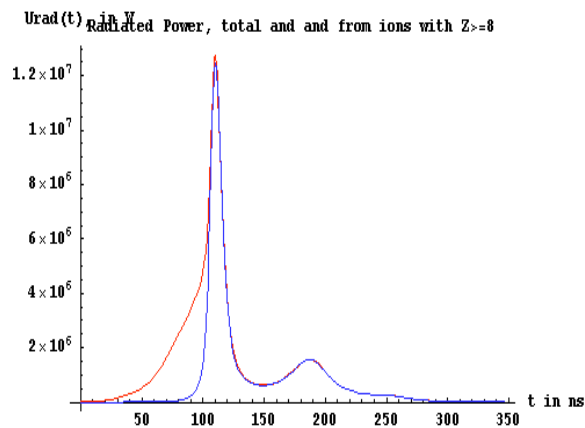


$Ziout(t)$

Mean Ionisation stage outer gas



Radiation



**Good agreement of transient radiation with experiments,
⇒ Optimization of CE**

Disadvantages of Xenon-discharges:

- Xenon is “bad” radiator, too much out of band radiation, CE only $\sim 0.5\%$
 - Would require not tolerable input powers for production tool
- Bypass currents outside pinch-discharge difficult to suppress
- Cathode erosion $\Rightarrow$
 - Change of pinch-shape $\Rightarrow$ impact on etendue
 - Limited in power

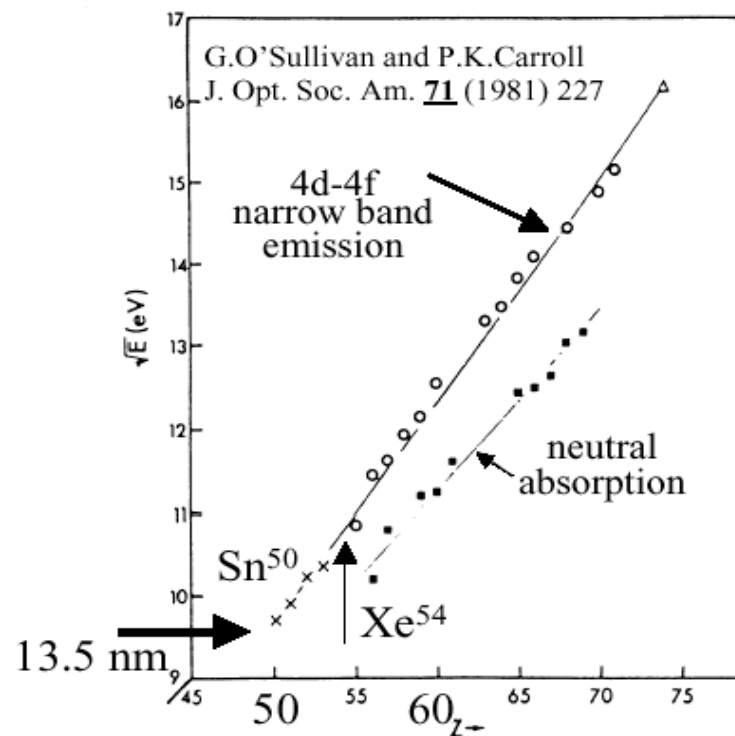
Cathode hole erosion



A good **EUV** radiator must have many lines in **inband** regi

- half filled outer shells with high angular momentum
- Li^{2+} has only one (thick) line 2p-1s line at 13.5 nm
- 4f energy levels scale with nuclear charge,
little dependence on Ionization stage (O'Sullivan) :

Xe $\Rightarrow$ Sn



wavelength of 4d-4f
narrow band emission

= determined by
atomic number

for 13 nm
Z=50 is the best
efficiency larger than
10% could be expected

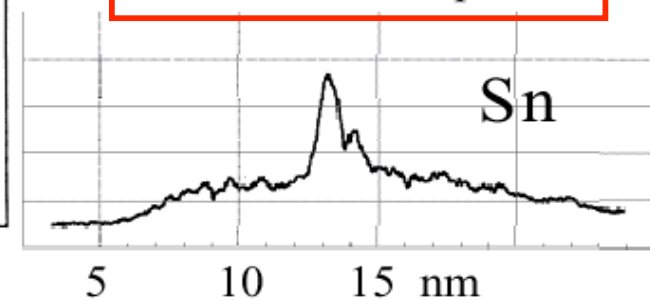
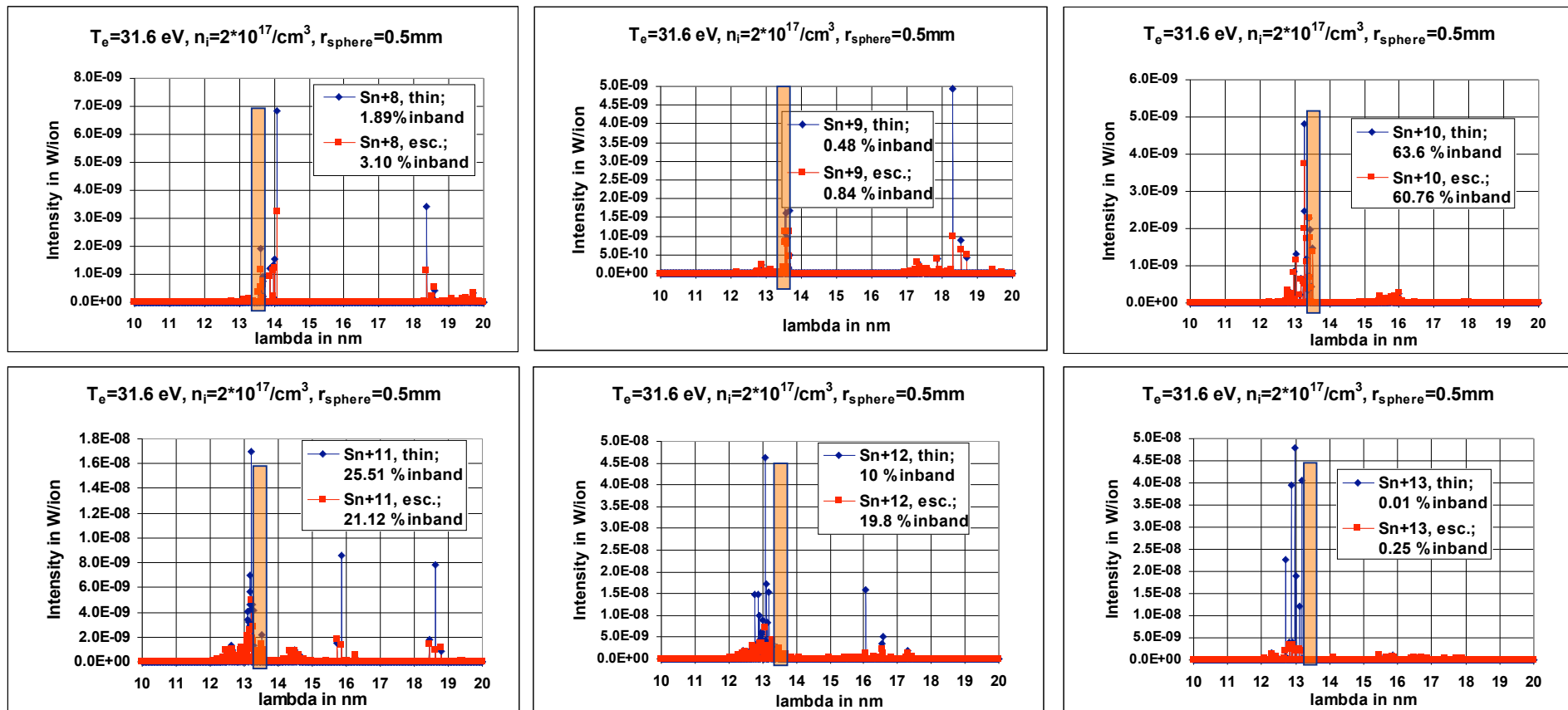


Fig. 5. Dependence of 4d-4f transition energies on atomic number Z. Open circles, this paper (Table 1); crosses, data from plasmas of tin through iodine; open triangles, assigned to tungsten in Tokamak plasma⁹; filled squares, absorption of neutral vapors.¹⁰

Tomie et.al. (Univ.Tokyo / Nikon),
Sematech EUV Source Workshop 2000

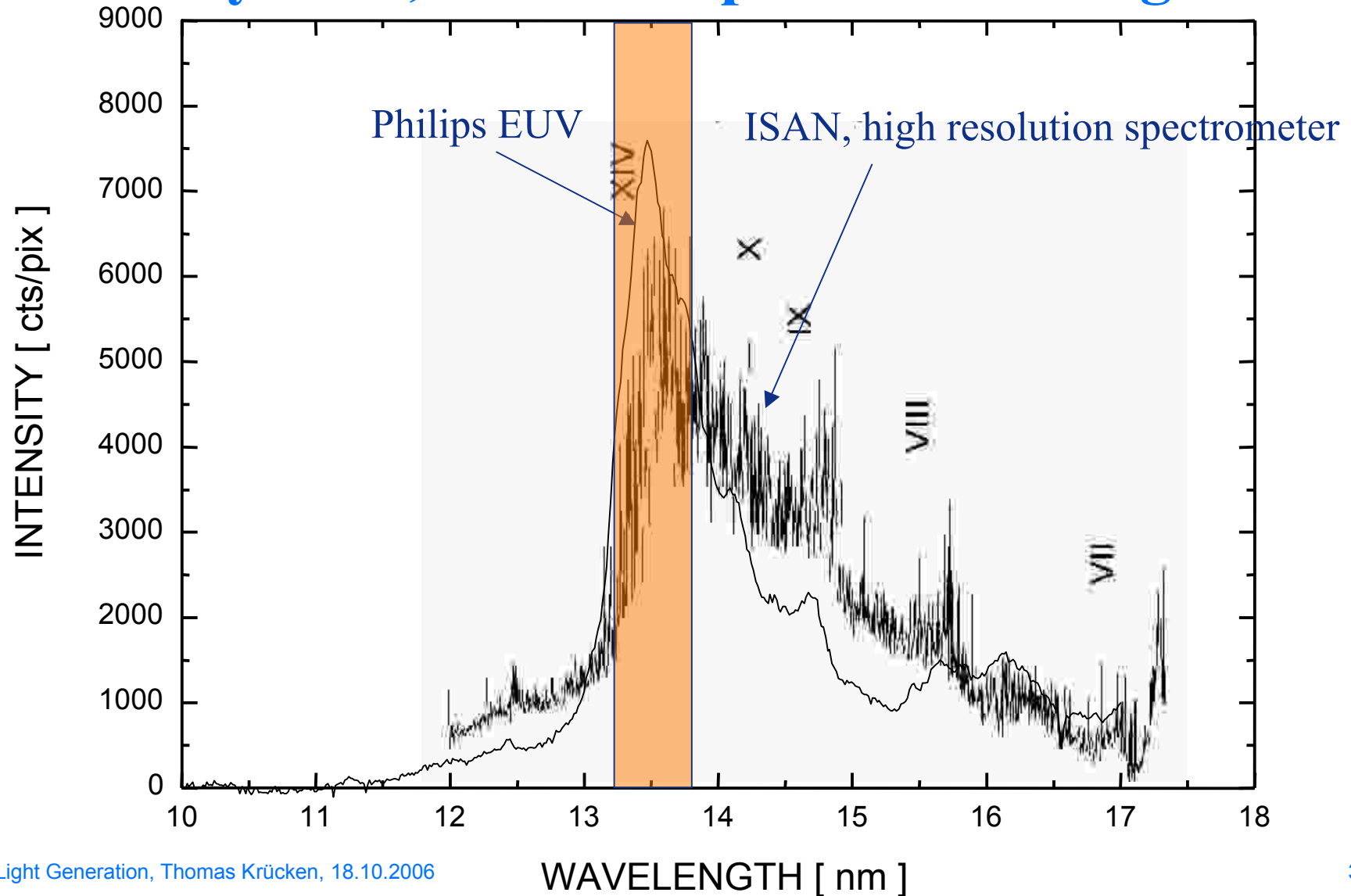
ADAS-Spectra of Tin ions Sn^{+8} - Sn^{+13}



Many different ions have many energy levels and strong 4d-4f transitions near 91 eV, also 5p-4d lines from some ions

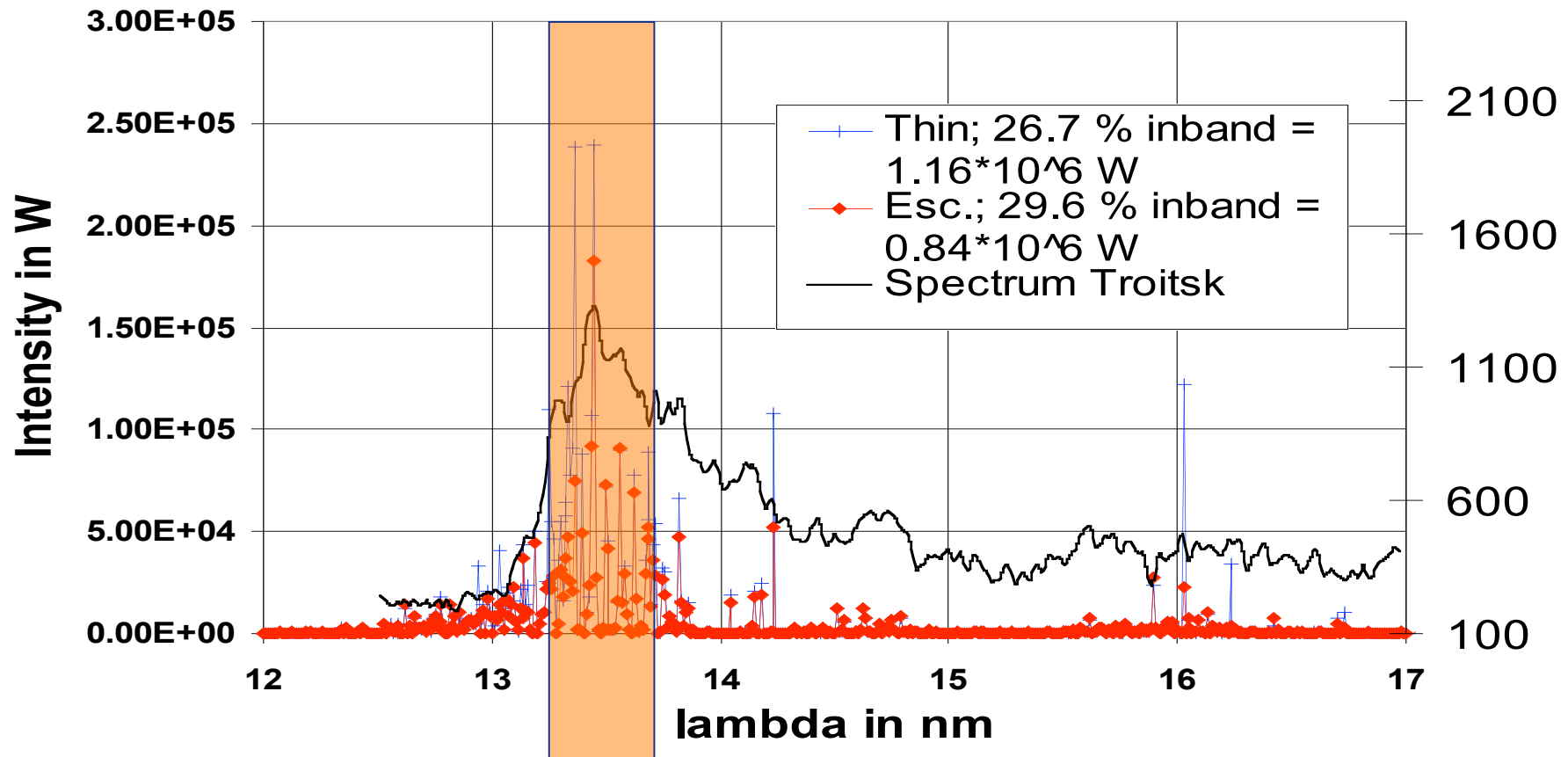
Measured Tin EUV spectra

Many lines, almost impossible to assign



Spectrum of Tin ion mix

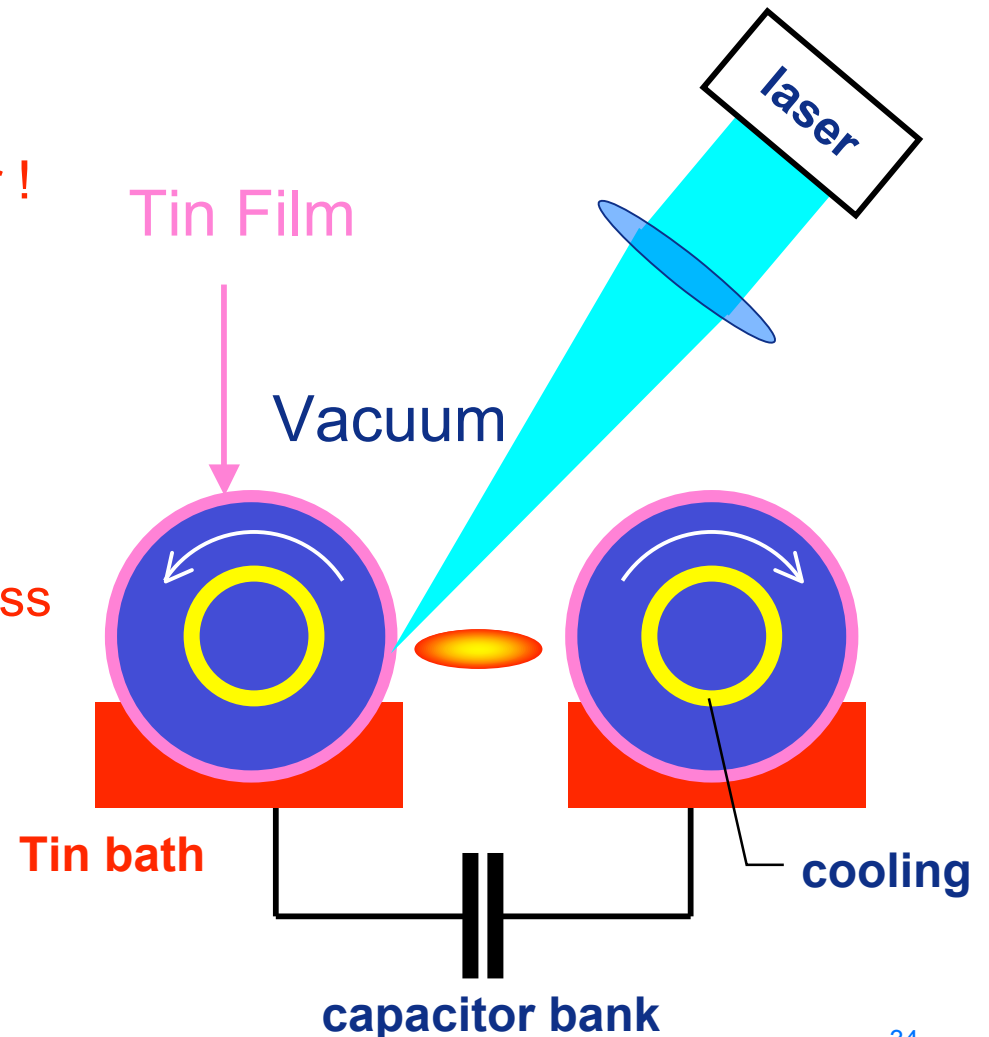
10^{14} Sn ions at $T_e=31.6$ eV, $n_i=2 \cdot 10^{17}/\text{cm}^3$, $r=0.5\text{mm}$;
 15% Sn^{+8} , 32% Sn^{+9} , 36% Sn^{+10} , 13% Sn^{+11} , 2% Sn^{+12}



Inband spectral efficacy near 13.5 nm ~ 5 times better than Xe !!!

New High Power Source Concept

- Laser Triggered Vacuum Spark
- Rotating electrodes
 - ⇒ Scalability to very high power !
- Regenerating liquid tin surface
 - ⇒ Electrode erosion problem fundamentally solved !
- Liquid metal cooling
 - ⇒ Very efficient to remove excess heat !
- CE ~ 2% achieved



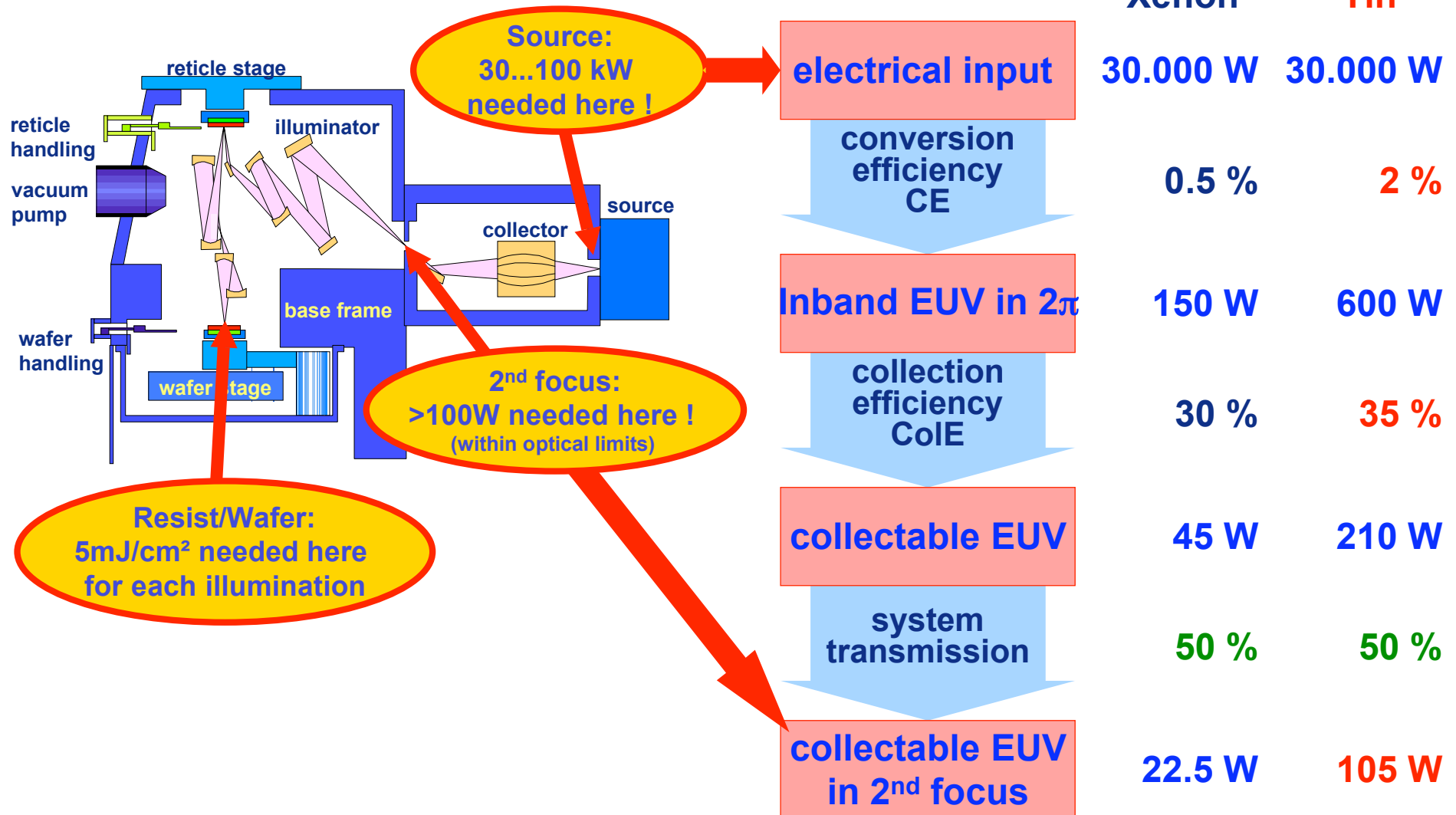
Very difficult to model plasma

- Laser ablation + Vapor expansion into vacuum
 - highly inhomogeneous density profile in space and time
 - Self absorption of Laser light $\Rightarrow$
 - Plasma heating/ionization
 - Reduced ablation
- Ignition when first ablated material reaches other electrode
- High current phase:
 - Further evaporation of Tin from electrodes
 - Thermal expansion and magnetic compression
 - Electrical current profiles/Skin effect ...
 - Strong inhomogenities in space (also axial) and time of
 - Density
 - Temperatures
 - Ionization stage
 - Strong self absorption of emitted (inband!) radiation
 - Instabilities

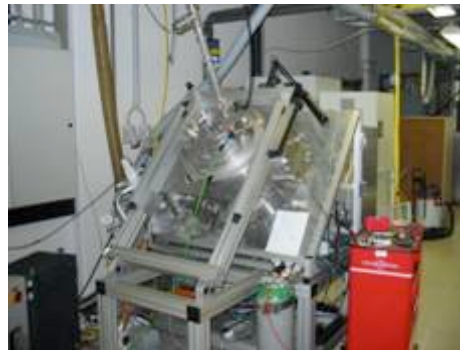
Problems of Tin-discharge

- Debris, Tin will condensate everywhere !
- Tin must be kept away from first optical elements (collector), only ~15 cm away from discharge
 - Tin layers on collector < 1 nm !!!
 - Debris Mitigation required
 - Discharge operates in vacuum
 - EUV transparency requires also vacuum
 - Cleaning of optical elements
- Many engineering aspects

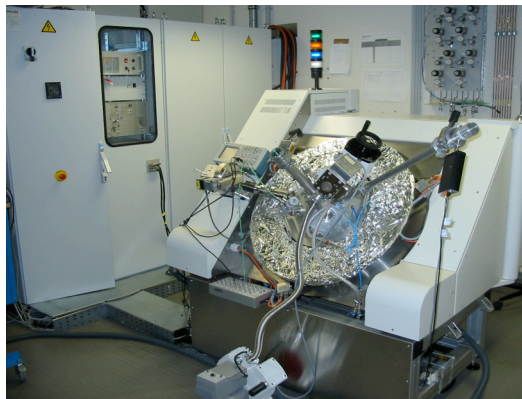
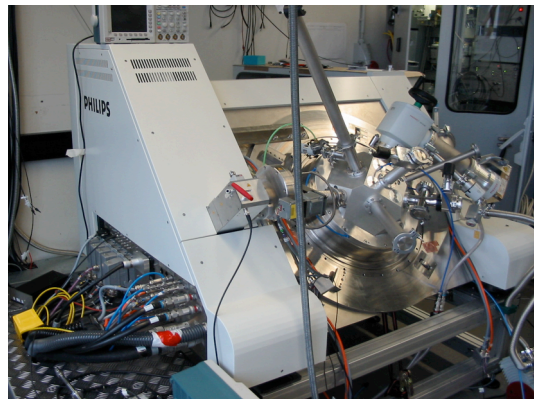
Throughput model for a commercial tool, 80 wafers/hour



Experimental and Demo sources

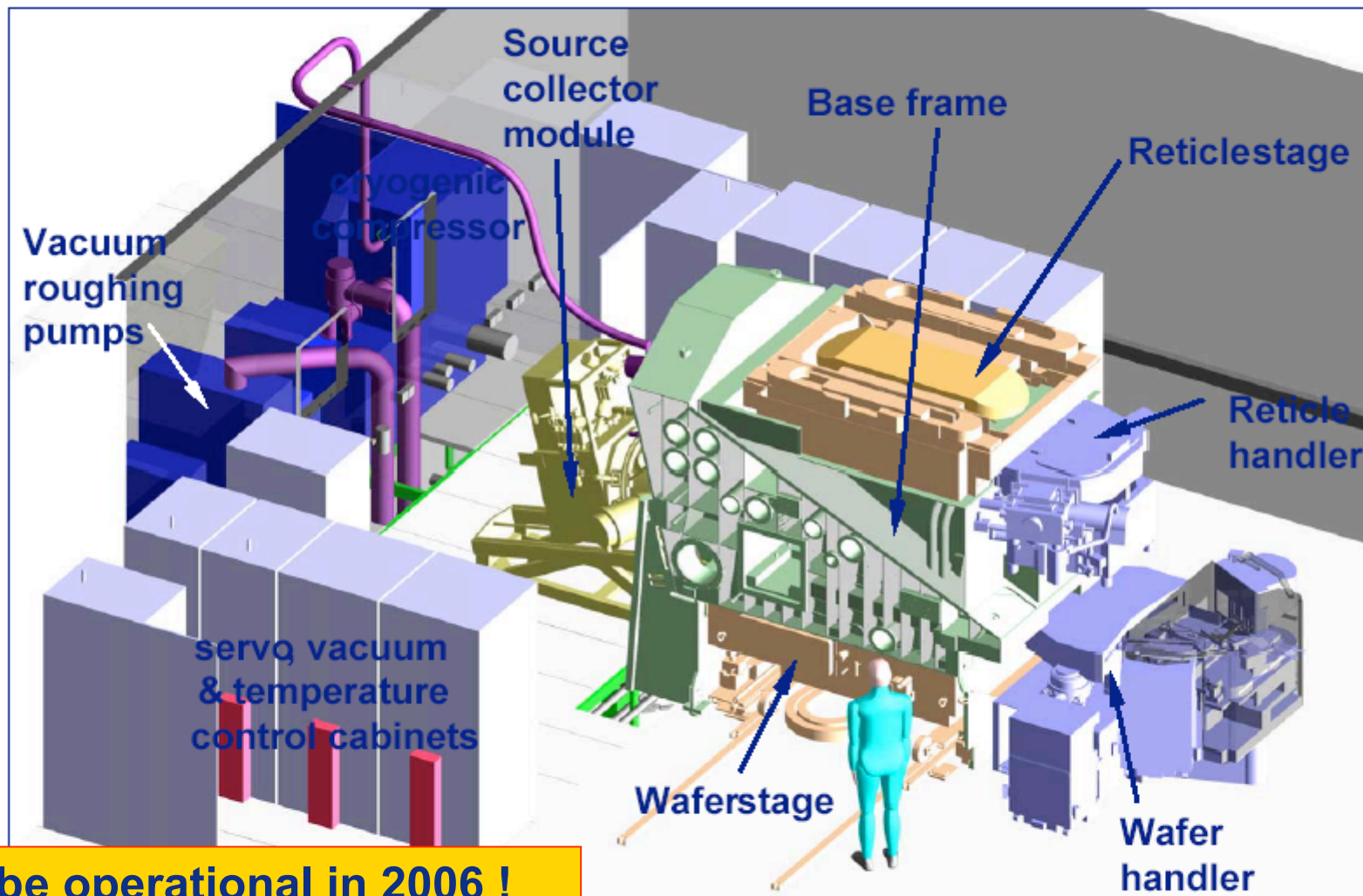


Source research and development



Commercial grade source

Alpha Demo Tool in Building 9



To be operational in 2006 !

Key value drivers for light source:

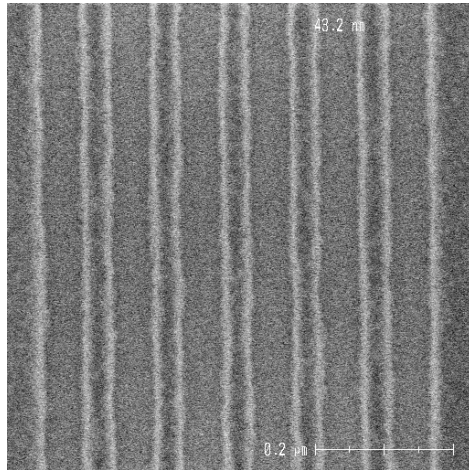
- Power → tool throughput
- Lifetime → tool uptime



ASML

Excellent Resolution and Line Edge Roughness

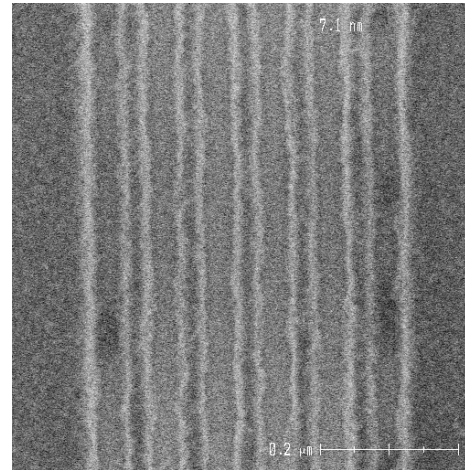
50 nm L/S



LER = 2.7 nm

ave TF LER = 4.0 nm

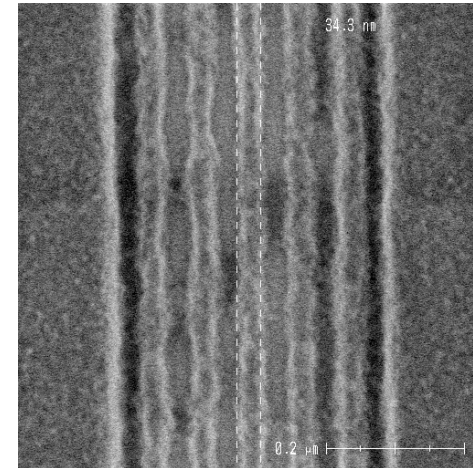
40 nm L/S



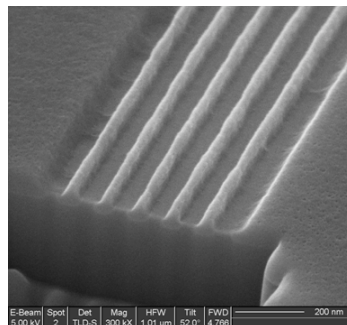
LER = 5.1 nm

ave TF LER = 6.1 nm

35 nm L/S



FIB Cross
section: 50
nm L/S resist
profile



Resist: MET-2D, ~18 mJ/cm²
NA=0.25
 $\sigma = 0.5$ (conventional illumination)
no process development yet



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